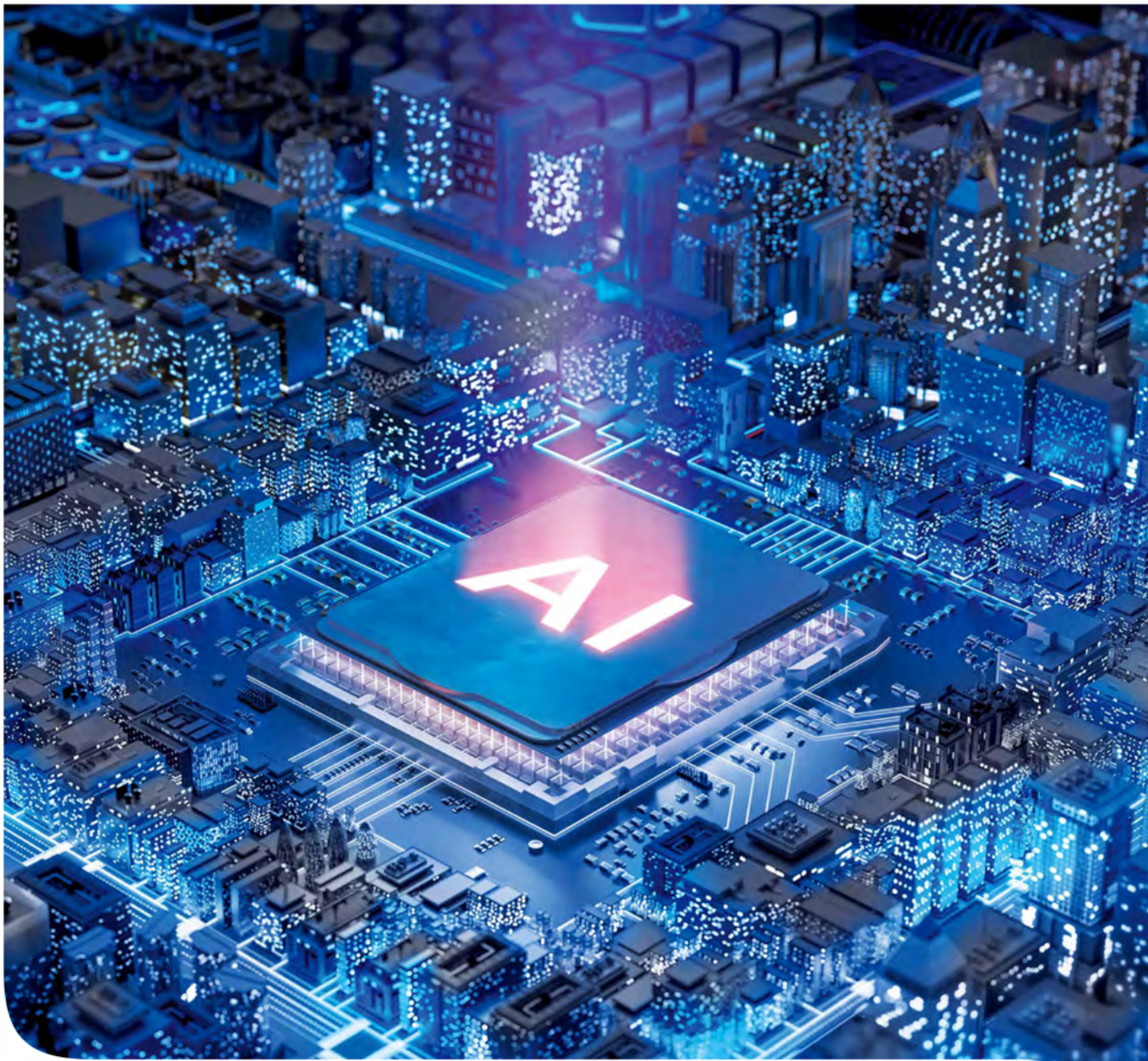


NEXCOM products are available at:

FORTEC
INTEGRATED



2025 Intelligent Platform & Service in Smart City Product Selection Guide

About NEXCOM

Intelligent Platform & Service in Smart City

Founded in 1992, NEXCOM is committed to being your trustworthy partner in building the intelligent business. NEXCOM makes the difference by utilizing its industrial computing experience, a highly talented R&D team, strong world-class ODM services, and rapid support to customers. NEXCOM has worldwide customers from more than 50 countries, and we never stop growth with our business partners. As we accelerate towards the future, NEXCOM has been playing an important role in bringing intelligence & service in city.

NEXCOM's Intelligent Platform & Service(IPS) has extended and developed many products for use in AI, 5G, and smart city related applications. We're creating a safer working environment and saving operational costs through improvements in logistics for more efficient management. Through the application and development of 5G, a better internet experience can be realized. We support our business partners to further promote edge AI computing for IOT gateway, smart retail, packing surveillance system, smart vending machine...etc.

We focus on developing practical technologies, and constant growth brings us many advantages in the smart city sphere:

- Superior power designed for uninterrupted operations
- Smart and effective designs, resistant to extreme environments
- Various communication module options (LTE, 5G & Wi-Fi)
- Reserve expansion space for extend functionality
- Elegant appearance design integrated into smart city without any sense of inconsistency.

NEXCOM has the passion, hope and dedication to keep moving forward making daily lives better through innovation. NEXCOM is forging ahead into the future and making it a success with our business partners!



Semi-Outdoor

Indoor



Indoor Product Series



Neu-X Series

Edge Computing System

- Fanless & Compact Design
- Just-fit IO
- Power adaptor Included
- Scalable with 5G/LTE, Wi-Fi & BT



AIEdge-X Series

Edge AI Computing System

- Designed for Edge AI applications
- Optional NVIDIA® GPU card, NVIDIA® Jetson Orin™ and Hailo module add-ons
- Scalable with 5G/LTE, Wi-Fi & BT



XPPC Series

Embedded Touch Computer

- Slim & Fanless Design
- Anti-Fingerprint coating
- Easy Clean-Flat Screen & IP65 in front
- Multi - PCAP touch
- Scalable with 5G/LTE, Wi-Fi & BT

Semi-Outdoor Product Series



NDiS Series

Visual Edge Computer

- Fanless & Compact Design
- Wide Temperature: -20 °C to 60 °C
- Wide Input Voltage: +12V to 24V DC
- Scalable with 5G/LTE, Wi-Fi & BT



HPPC Series

High Brightness Embedded Touch Computer

- Sunlight Readable
- AF+AG Coating
- Auto Dimming
- Solar resistance
- Scalable with 5G/LTE, Wi-Fi & BT



X series

Embedded Computing Board

- Standard 3.5" & Mini-ITX Form Factor
- Rich IO design
- Wide Temperature: -40 °C to 85 °C
- Scalable with 5G/LTE, Wi-Fi & BT



Core Competencies

Committed to Customer Success
Co-Creating Smarter Business in Digital Transformation Era

Premium Computing Design Capability

Computing power applications, which is why NEXCOM offers a wide range of computing platform to meet different needs.

- Intel Atom® platform: Apollo Lake, Elkhart Lake, Alder Lake-N, Amston Lake & Twin Lake
- Intel® Core™ i platform: Coving Core i -S/H/U & Core Ultra AI PC
- NVIDIA® Jetson Orin™ NX/Nano integrated
- AMD Ryzen Platform
- ARM Platform

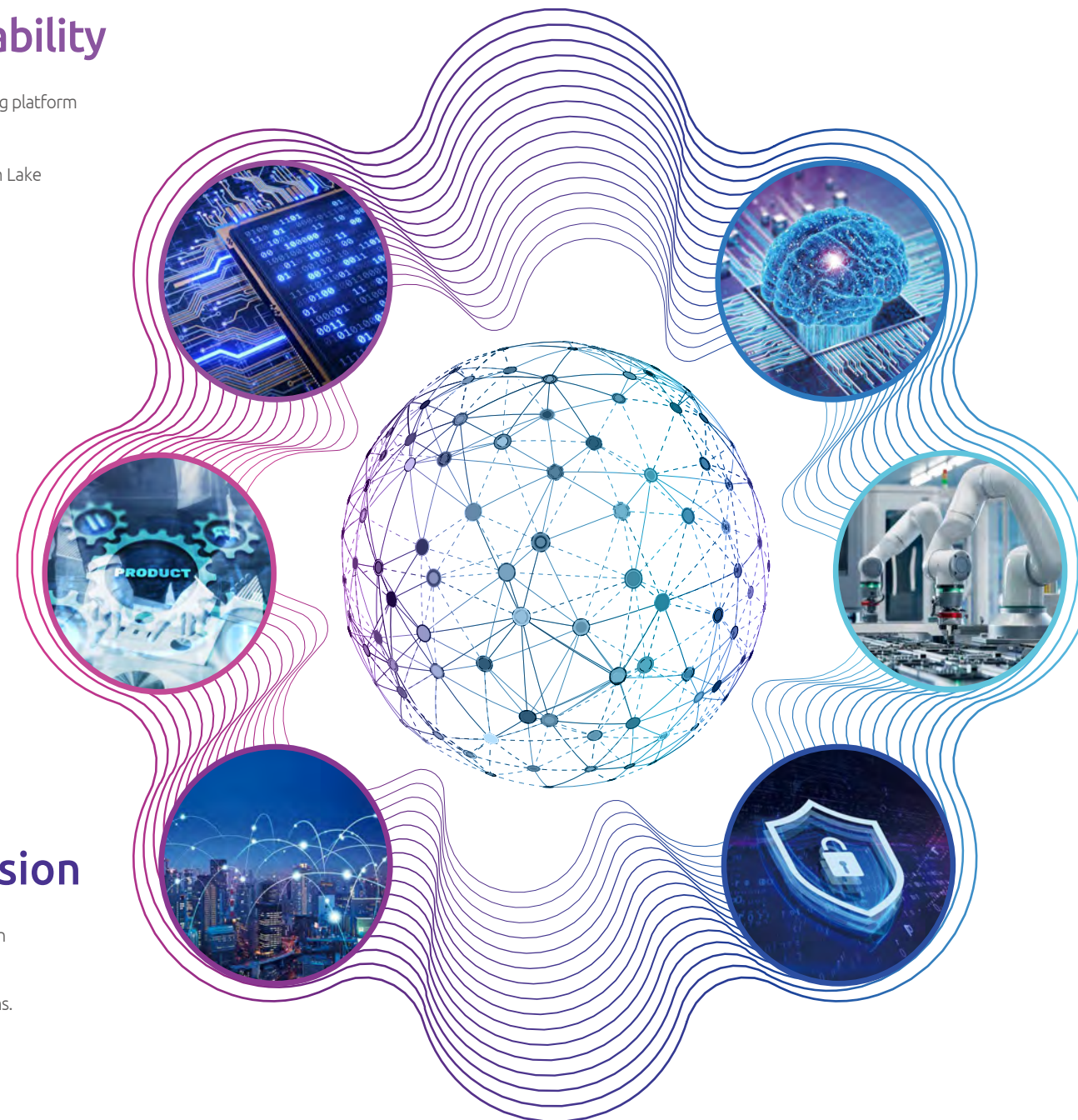
Reliability Quality

- Fanless design: Resistant to extreme environmental conditions
- Product approval: Rigorous internal verification process
- Certification: Compliant with worldwide EMC/EMI and Safety certification by request.
- Digital and Green Manufacturing: Compliant with ISO 14067

Wireless Communication Expansion

For the diverse range of wireless applications, NEXCOM specializes in RF communication expansion. We offer a comprehensive series of proprietary mini-PCIe/M.2 modules that provide users with maximum flexibility in optimizing wireless connectivity configurations.

- 4G LTE, 5G
- Wi-Fi
- Bluetooth



AI Technology

- NVIDIA® (GeForce/Quadro, Jetson Orin™ NX)
- Intel x OpenVINO™
- AMD x ROCm™
- Hailo AI accelerator Module (M.2 & mini-PCIe)
- Co-work with partners in driving deeper customer engagement in AI + edge computing applications.
- Provide edge processing and AI capabilities to software partners/developers for innovation and the creation of new business models.

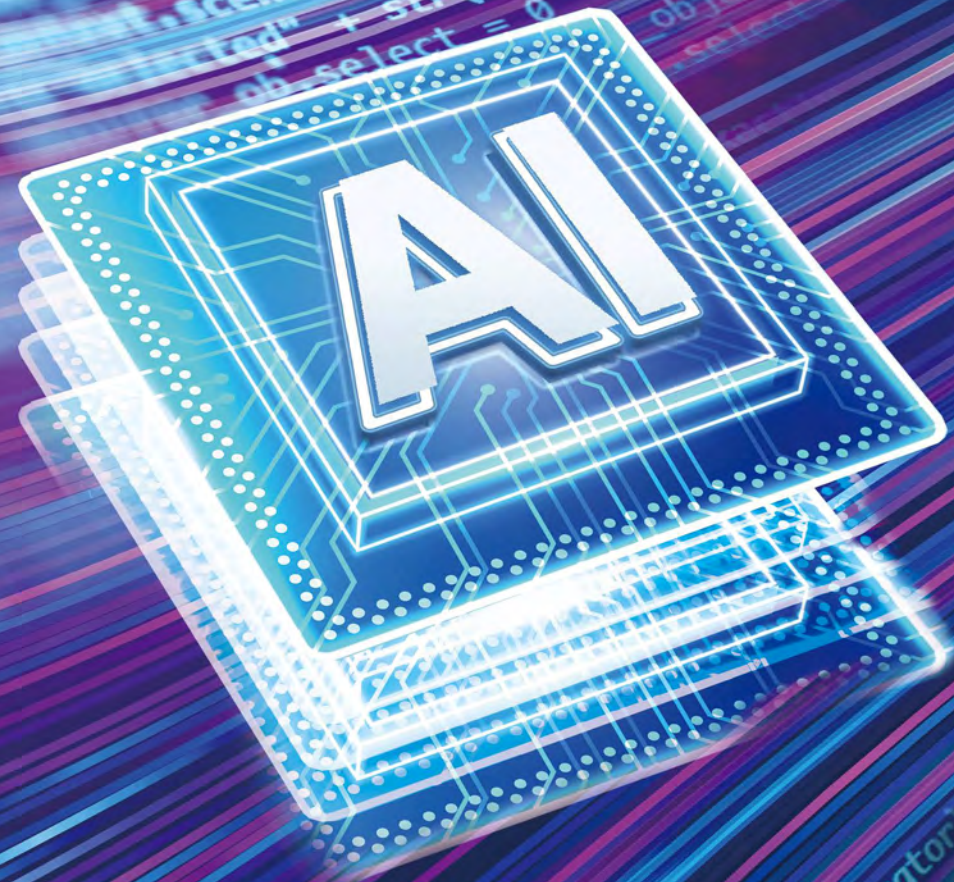
OEM/ODM Services

- Over 30 years of experience in industrial-grade computer design and Manufacturing
- Proven design capabilities in customized system and software integration
- Customization service on BIOS, mainboard and system design
- Certificated, 100%-owned manufacturing facilities in Taiwan
- Expertise in industrial PC solution with vertical domain know-how
- Accommodates small to medium quantities with fast time-to-market delivery

Software Solutions

- Customized BIOS
- Secure System Development (TPM, Secure Boot)

Edge AI Solution



NDiS B363

Visual Edge Computer Powered by Intel® Arrow Lake-U Processor (up to 22.5 TOPS)

- Support 2 independent 4K@60Hz display output
- 3 x USB 2.0, 1 x USB 3.2 Gen 1x1, Type A
- 2 x RS-232/422/485
- 1 x GbE LAN, 1 x 2.5G GbE LAN
- 3 x M.2 socket Key B/E/M
- Power Input: 12~24V DC-in
- Operating Temperature: 0°C to 60°C



NDiS B362

Visual Edge Computer Powered by Intel® Meteor Lake-U Processor (up to 22.4 TOPS)

- Support 2 independent 4K@60Hz display output
- 3 x USB 2.0, 1 x USB 3.2 Gen 1x1, Type A
- 2 x RS-232/422/485
- 1 x GbE LAN, 1 x 2.5G GbE LAN
- 3 x M.2 socket Key B/E/M
- Power Input: 12V DC-in
- Operating Temperature: 0°C to 60°C



AIEdge-X@80

Edge AI Computer NVIDIA® Jetson Orin™ NX (up to 100 TOPS)

- NVIDIA® Jetson Orin™ NX 16GB (100 TOPS)/8GB (70 TOPS)
- 1 x HDMI, 2 x COM port, 4 x USB, 1 x USB OTG
- 1 x M.2 3042/3052 Key B for 5G/LTE, 1 x M.2 2280 Key M for Storage
- Extended Operating Temperature -20 to 60 °C
- DC in 24V with 3 pin phoenix terminal block



X201

3.5" Embedded Computing Board, Intel® Meteor Lake-U Core™ Ultra processors

- 2 x DDR5 5600 262-pin SO-DIMM, non-ECC, unbuffered, up to 96GB
- 2 x HDMI 2.0, up to 4096 x 2160@60Hz
- 1 x 2.5GbE RJ45 Port, Intel® i226
- 1 x GbE RJ45 Port, Intel® I219
- 1 x USB 3.2 Gen 1 x 1, Type-A
- 3 x USB 2.0
- +12V DC-in



X203

3.5" Embedded Computing Board, Intel® Arrow Lake-U Core™ Ultra processors

- 2 x DDR5 5600 262-pin SO-DIMM, non-ECC, unbuffered, up to 96GB
- 2 x HDMI 2.0, up to 4096 x 2160@60Hz
- 1 x 2.5GbE RJ45 Port, Intel® i226
- 1 x GbE RJ45 Port, Intel® I219
- 1 x USB 3.2 Gen 1x1, Type-A
- 3 x USB 2.0
- +12V DC-in

2025 New Products

NDiS B561

Visual Edge Computer Powered by 14,13 & 12th Gen Intel® Core™ Processor

- Support 3 independent 4K@60Hz display output
- 8 x USB 3.2
- 1 x RS-232/422/485, 3 x RS232
- 1 x GbE LAN, 2 x 2.5G GbE LAN
- 3 x M.2 socket Key B/E/M
- Power Input: 12~24V DC-in
- Operating Temperature: -20°C to 60°C

NDiS B561 - POE

Visual Edge Computer Powered by 14,13 & 12th Gen Intel® Core™ Processor

- Support 3 independent 4K@60Hz display output (one port support up to 8K)
- 8 x USB 3.2
- 1 x RS-232/422/485, 3 x RS232
- NDiS B561S: 1 x GbE LAN, 2 x 2.5G GbE LAN
- 3 x M.2 socket Key B/E/M
- Power Input: 24V DC-in
- Operating Temperature: 0°C to 40°C

NDiS B561S

Visual Edge Computer Powered by 14,13 & 12th Gen Intel® Core™ Processor

- Support 2 independent 4K@60Hz display output
- 2 x USB 3.2, 4 x USB2.0
- 1 x RS-232/422/485, 3 x RS232
- 1 x GbE LAN, 1 x 2.5G GbE LAN
- 3 x M.2 socket Key B/E/M
- Power Input: 12V DC-in
- Operating Temperature: 0°C to 50°C

NDiS B361

Visual Edge Computer Powered by Raptor lake-U Processor

- Support 2 independent 4K@60Hz display output
- 3 x USB 2.0, 1x USB 3.2 Gen 1x1, Type A
- 2 x RS-232/422/485
- 1 x GbE LAN, 1 x 2.5G GbE LAN
- 3 x M.2 socket Key B/E/M
- Power Input: 12~24V DC-in
- Operating Temperature: 0°C to 60°C

NDiS B339

Visual Edge Computer Powered by Intel® Processor X-series

- Support Intel Atom® x 7000 RE Series SoC processors
- 2 x 2.5GbE LAN
- 4 x USB 3.2 Gen1x1, Type A
- 1 x RS232/422/485, 1 x RS232
- Power Input: 12~24V DC-in
- Operating Temperature: -20°C to 60°C

Neu-X60

Edge Computing System Power by Intel® Alder Lake N50 processor

- Intel® Processor N50
- Small footprint in Palm size
- Pre-installed 4GB memory, Pre-installed 128GB M.2 storage
- Support 1 x Intel I226-V 2.5GbE LAN, 1 x HDMI, 1 x RS232/422/485, 2 x USB3.2
- 1 x minPCIe full size for optional wireless module
- Operating Temperature: 0°C to 40°C

Neu-X304 series

Edge Computing System Powered By 14,13 & 12th Gen Intel® Core™ Processor

- 14/13/12th Gen Intel® Core™ i9/i7/i5/i3 processors, up to 35W
- Dual channel DDR5 SO-DIMM, max up to 64GB
- 3 x HDMI2.0 (4K@60Hz), 2 x Intel® LAN, 2 x COM ports, 8 x USB port
- Support Intel® AMT technology (Q670E only)
- Power input: 12V DC or 12~24V DC (Q670E only)
- Operating Temperature: -5°C to 45°C

Neu-X102-N50

Edge Computing System Powered by Intel® Processor N50

- Slim compact chassis and fanless design
- 1 x DDR4 SO-DIMM socket, max up to 16GB
- 2 x HDMI2.0 (4K@60Hz), 2 x 2.5GbE LAN, 4 x USB3.2 Gen2
- 1 x M.2 2242 Key M for support PCIe & SATA storage device
- Power Input: 12V DC-in
- Operating Temperature: -5°C to 50°C

Neu-X102-N97/i3

Edge Computing System Powered by Intel® Processor N97 & Intel® Core™ Processor, i3-N305

- Slim compact chassis and fanless design
- 1 x DDR4 SO-DIMM socket, max up to 16GB
- 2 x HDMI 2.0 (4K@30Hz), 2 x 2.5GbE LAN, 4 x USB3.2 Gen2
- 1 x M.2 2242 Key M for support PCIe & SATA storage device
- Power Input: 12V DC-in
- Operating Temperature: -5°C to 50°C


2025 New Products



XPPC16-10N97

15.6" TFT FHD 16:9 Slim Bezel Embedded Touch Screen Computer Powered by Intel® Processor N97


- 1 x DDR4 260-pin SO-DIMM, up to 16 GB
- 1 x M.2 2242 Key M, support PCIe x1 & SATA for storage
- 1 x full-size mini-PCle, available for WiFi/LTE module
- Power Input: 12V DC-in
- Operating Temperature: 0°C to 50°C



XPPC10-10N97

10.1 FT WXGA 16: 10 Slim Bezel Embedded Touch Screen Computer Screen Powered by Intel® Processor N97


- 1 x DDR4 260 pin SO DIMM, up to 16 GB
- 1 x M.2 2242 Key M, supports PCIe x 1 & SATA for storage
- 1 x full size miniPCle, available for WiFi/LTE module
- Power Input: 12V DC-in
- Operating Temperature: 0°C to 50°C



HPPC15-10X7211

15" XGA 4:3 High Brightness Panel PC Powered by Intel® Amston Lake X7211 Processor


- Optical Bonding with Anti-UV & IR treatment
- AF & AG surface treatment
- With light sensor for auto dimming
- power input: 24V DC-in
- Operating Temperature: -20°C to 60°C



X102

3.5" Embedded Computing Board, Intel® Alder Lake N Processor


- 1 x DDR4 SO-DIMM socket, max up to 16GB
- Support 2 x HDMI 2.0 output, 4K@30Hz and 1 x eDP or LVDS
- 2 x 2.5GbE LAN, 4 x USB 3.2 Gen2
- 1 x M.2 2242 Key M for supporting PCIe & SATA storage device
- 1 x mini-PCle slot support Wi-Fi and LTE module



X103

3.5" Embedded Computing Board, Intel Atom® x6000E Series Processors


- 1 x DDR4 SO-DIMM socket, up to 32GB
- Support 1 x HDMI 1.4, 4K30Hz and a dual channel 18/24-bits LVDS connector, up to 1920 x 1080@60Hz
- 3 x 2.5GbE LAN, 4 x USB port, 6 x COM
- 1 x M.2 Key B , 1 x M.2 Key E, 1 x mini-PCle slot
- Support dual power input, 12/24V DC-in



X104

3.5" Embedded Computing Board, Intel® Twin Lake N Processors

- 1 x DDR4 SO-DIMM socket, max up to 16GB
- Support 2 x HDMI 2.0 output, 4K@30Hz and 1 x eDP or LVDS
- 2 x 2.5GbE LAN, 4 x USB 3.2 Gen2
- 1 x M.2 2242 Key M for supporting PCIe & SATA storage device
- 1 x mini-PCle slot support Wi-Fi and LTE module



X202

3.5" Embedded Computing Board, 13th Generation Intel® Core™ Processors

- 2 x DDR5 SO-DIMM, up to 96 GB
- 2 x HDMI 2.0, up to 4096 x 2160@60Hz
- 1 x 2.5GbE RJ45 Port, Intel® i226
- 1 x GbE RJ45 Port, Intel® I219
- 1 x USB 3.2 Gen 1 x 1, Type-A
- 3 x USB 2.0
- Power Input: 12V DC-in



X304-MTX

Mini-ITX Embedded Computing Board Powered by 14,13 & 12th Intel® Core™ Processor

- 14, 13 & 12th Intel® Core™ LGA 1700 socket type processors, 35W
- Dual channel DDR5 SO-DIMM, max up to 64GB
- 3 x HDMI 2.0, 1 x LVDS (supported by Q670E)
- M.2 2280 Key M for storage, M.2 2230 Key E for Wi-Fi,
- M.2 3042/3052 Key B for LTE/5G
- Dual Intel® LAN ports

Riverside Revolution: NEXCOM's Neu-X102-N50 Transforms Tourist Information

Along the bustling banks of the Thames in London, sleek digital totems now stand as silent guides for curious visitors. These modern sentinels display real-time boat schedules, weather updates, and a wealth of local information, transforming the riverside experience. At the heart of this urban evolution lies NEXCOM's powerful Neu-X102-N50, the driving force behind these innovative information hubs.

These innovative information totems are revolutionizing visitor experiences in waterfront destinations citywide. While their exteriors may vary to suit local aesthetics, their core remains constant: NEXCOM's powerful edge computing system, the Neu-X102-N50.

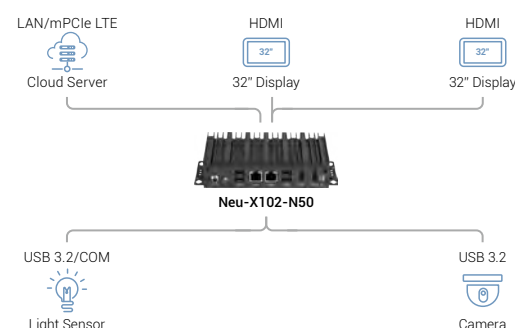
At the heart of these totems lies impressive technology tailored for outdoor applications. The Neu-X102-N50 boasts an Intel Alder Lake-N N50 processor and up to 16GB of RAM, ensuring smooth performance even in challenging environments. Its ability to operate in temperatures from -5°C to 50°C makes it suitable for diverse climates.

The Neu-X102-N50's technical prowess extends beyond its processor. With support for up to two HDMI ports for playing vivid content, it can deliver eye-catching visuals to attract and inform visitors. Its M.2 & mPCIe slots allow for expandable storage, LTE & Wi-Fi 6 capability, ensuring ample space for rich content and lightning-fast wireless connectivity. These features enable the totems to serve as comprehensive information hubs, capable of handling high-traffic areas with ease. Tourists interact with vibrant 32-inch touchscreen displays, accessing a wealth of information beyond just schedules and

weather. Local attractions, dining recommendations, and even real-time air quality data are at their fingertips. The system's dual 2.5GbE LAN ports and 4G LTE connectivity ensure that this information is always current and readily available. Through a USB light sensor and COM port, the totem can automatically adjust its brightness, ensuring all information remains readable in varying light conditions while contributing to the system's energy efficiency, aligning with modern urban sustainability goals. For totem operators, remote management capability is key. They can update content and perform system maintenance through LAN or LTE, significantly reducing operational costs and ensuring efficient management.

These systems improve the visitor experience and provide valuable data insights for urban planning and tourism management. Through cameras connected via USB 3.2 high-bandwidth ports, the Neu-X102-N50 ensures smooth capture and transmission of data, enabling real-time monitoring and analysis of visitor flows. This advanced capability allows city planners and tourism officials to make informed decisions, optimize resource allocation, and enhance overall urban mobility, while maintaining a seamless and enjoyable experience for tourists and locals alike.

The Neu-X102-N50 represents a significant step forward in smart city technology, blending seamlessly into urban landscapes while providing an essential service to tourists and locals alike. As more areas of the city adopt this technology, we can expect to see a transformation in how people interact with and navigate waterfront destinations, ushering in a new era of informed and engaged urban tourism.



Neu-X102-N50

- Intel® processors N50 (Alder Lake-N), Intel 7 process
- Slim compact chassis and fanless design
- Support 2 x HDMI 1.4b output, 4K@30Hz
- Richful I/O connectivity: 2 x 2.5GbE LAN, 4 x USB 3.2 Gen2
- 1 x mini-PCIe slot support Wi-Fi and LTE module



Revolutionizing Health Monitoring: A Self-service Health Check Kiosk Success Story with NDiS B338

In bustling cities of APAC, a revolutionary change is taking place in the way citizens approach their health and well-being. A beacon of wellness emerged, a state-of-the-art health check kiosk powered by NEXCOM's NDiS B338 embedded system, was designed to offer accessible and convenient, and comprehensive health assessments to anyone in need.

The Challenge

With a growing population spread across the cities and remote areas, there was a pressing need for a more efficient and accessible way to monitor health. Traditional methods were time-consuming and often required visits to medical facilities, which could be daunting for many.

The Solution

The answer came in the form of a cutting-edge self-service health check kiosk, built around the robust NEXCOM NDiS B338 embedded system. Tailored to meet the intricate needs of the market, NDiS B338 features 3 HDMI 2.0 outputs, 6 USB ports, 4 serial ports, and audio output, ensuring a versatile and userfriendly interface for seamless integration.

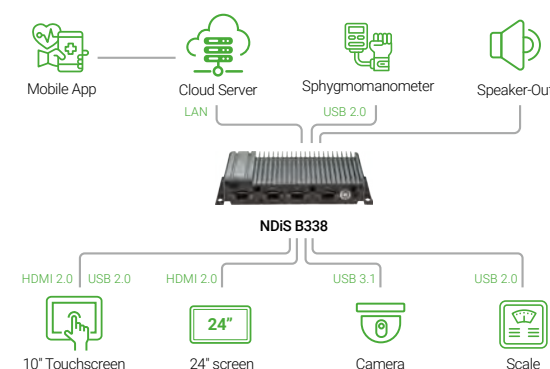
The Technology

The NDiS B338 stands out with its Intel® Celeron® J6412 Quad core high-performance processor and wide operating-temperature support from -20°C to 60°C. HDMI 2.0 outputs deliver highdefinition visuals, guiding users through the health check process with interactive prompts and educational content. The multiple USB ports allow for the attachment of various health monitoring devices, enabling a full spectrum of checks, from blood pressure to glucose levels.

Serial ports provide seamless connectivity for additional peripherals, while the speaker-out ensures clear audio instructions, making the kiosk accessible to all users, including those with visual impairments.

The Impact

Since its introduction, this self-service health check kiosk has seen widespread adoption, with users praising its ease of use and the immediate insights into their health. It has not only empowered individuals to take proactive steps towards their wellbeing but also reduced the burden on healthcare providers.



NDiS B338

- Intel® Celeron® processor J6412
- Support 3 x HDMI 2.0 output
- Support 12~24V DC input
- Compact and slim design (H: 38.8mm)
- 2 x DDR4 up to 32G
- 1 x M.2 2280 Key M for optional storage device
- 1 x M.2 3042/3052 Key B for optional LTE or 5G modules
- 1 x mini-PCIe for optional Wi-Fi and LTE
- Fanless design



AI and Advanced Tech Revolutionize Drive-Thru and Delivery for QSRs

The rapid increase in drive-thru and home delivery orders during the COVID-19 pandemic has spotlighted pressing operational challenges for quick-service restaurants (QSRs). While convenient for customers, these ordering methods introduce issues like order accuracy, traffic management, and technology integration that QSR owners must address. In response, digital transformation through AI and advanced technology can revolutionize processes to enable seamless operations and satisfied customers.

Key Operational Challenges

The spike in demand has led to extended wait times that jeopardize customer satisfaction. Managing the surge in order volume strains speed and accuracy across drive-thru and delivery. Hiring additional staff to handle extra traffic increases labor costs. Integrating technology for digital ordering and payments complicates backend systems.

Streamlined Operations and Enriched Experiences

Digital transformation is critical for QSRs navigating this landscape. Solutions like the Neu-X101 edge computer and XPPC10-100 touchscreen from NEXCOM offer efficient operations and improved customer experiences.

Neu-X101 Drive-Thru Controller for 24/7 Operational Excellence

The Neu-X101 serves as the drive-thru system's central controller,

facilitating connectivity with key components. This includes a 15" High-Brightness Display for order confirmation via HDMI, a camera for facial recognition through USB, and two-way audio communication via Mic-In & Audio-Out. LAN connectivity also ensures integration with the POS system. With its fanless design and reliable power, the Neu-X101 enables uninterrupted 24/7 operation, enhancing the overall drive-thru experience.

Boost Order Accuracy with the XPPC10-100's AI Integration

To ensure order accuracy, NEXCOM customers integrate the XPPC10-100 touchscreen computer with an AI system that automatically checks bag contents, minimizing errors that hurt satisfaction and sales. Powered by the slim XPPC10-100 touchscreen, staff can efficiently manage orders. Its user-friendly 10.1" projected capacitive touchscreen and Celeron J3455 CPU offer seamless performance. Connectivity includes 1x USB, 1x LAN, and 1x COM, while its IP65-rated front panel is dust and liquid resistant. USB barcode scanning improves precision. LAN connectivity with POS and back-end systems optimizes kitchen workflow.

By embracing digital transformation and cutting-edge technologies, QSRs can overcome drive-thru and delivery challenges, consistently providing exceptional customer experiences.

NEXCOM Empowers Automobile Manufacturers in Data Collection from Production Line to Customer Insights

A prominent European car manufacturer was searching for an all-encompassing solution to address its dual customer-facing and in-house needs. The ideal solution would easily push content in their car showrooms to engage customers and evaluate their interactions while simultaneously collecting and displaying data from the assembly line. NEXCOM promptly answered the client's call for help with a winning combination: the Neu-X300 edge computing system and XPPC10-100 touchscreen computer. With a wealth of I/O integrations for compiling and presenting critical information, these compact-sized and easily maintained computers were the best choice for the manufacturer's external and internal uses.

Collect data from end customers

Purposely built for multiple applications, the Neu-X300 provides superior processing power, supports three separate 4K HDMI signals, and features a fanless design. The manufacturer's particular choice of Intel's Core i7 fueled its eye-catching video wall, interactive signage counter, and information kiosk. Various software integrations extended the embedded player's capabilities beyond mass-audience signage to customized displays, utilizing audience measurement to detect customers' reactions and gauge interest, and RFID sensors to identify objects that customers grasped and consequently show responsive ads. The fanless design also

meant that the Neu-X300 was space-efficient, allowing the client to deliver powerful images and advertisements without the clutter of industrial-size computers.

Collect data from the production line

Not only did NEXCOM meet the automobile manufacturer's marketing and sales needs but also increased production accuracy and traceability through the XPPC10-100. The panel PC's system architecture enabled real-time data collection by including various I/O connections requisite for industrial environments such as the client's assembly lines. For example, it linked to ERP/MES systems and barcode scanners via USB, whereas its LAN ports provided data transmission and production line management. What's more, the XPPC10-100's IP65-rated front panel is protected against dust or water projections, ensuring that the client would avoid replacement expenses due to accidental damage.

Put the total solution at your fingertips

NEXCOM is the leader in providing IoT devices for customers' digital transformation needs.

When integrated with appropriate software, NEXCOM's comprehensive combinations, such as the Neu-X300 and XPPC10-100, are the ultimate fit for a multitude of applications, saving customers time and money.

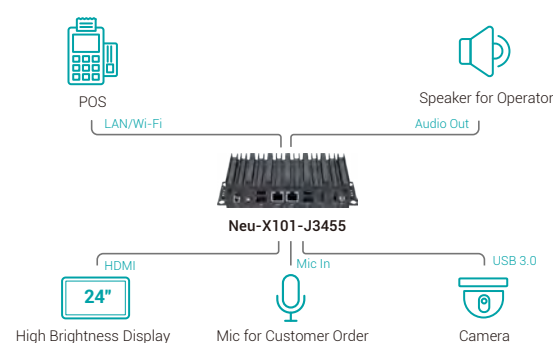


Figure 1: Drive-Thru Order & Customer Measurement

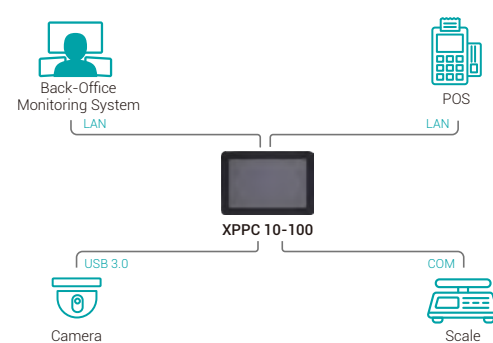
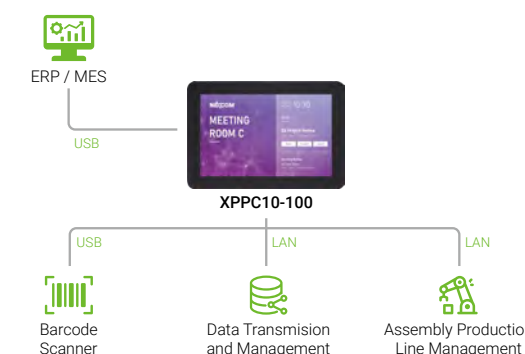
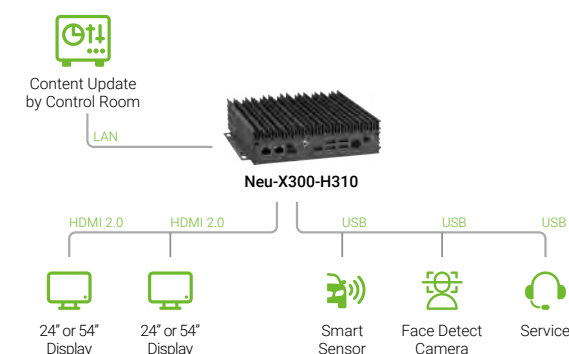


Figure 2: Smart Food Checking System



NEXCOM's Edge Computing System Brings Engaging Amusement Machine Experience

The amusement machine industry has been thriving for years, providing entertainment and educational options for people of all ages. As technology has advanced, the market has shifted to more immersive arcade machine experiences. Recently, there has been an increased demand for educational machines that offer interactive gameplay to help children learn. This is due to a desire for more effective and engaging learning, as well as a growing awareness of the benefits of early childhood education. As technology continues to advance, and new forms of entertainment and education emerge, the amusement machine market is expected to keep growing. The Neu-X101 from NEXCOM is an edge computer that meets this growing demand.

NEXCOM's Neu-X101 is a versatile device that can connect to various peripherals, including gaming controllers, joysticks, and high-resolution displays. It is powered by an Intel® Celeron® J3455 processor, providing sufficient computing power for immersive gaming experiences. With HDMI connections, manufacturers can link up to 4K displays, giving customers a visually stunning gaming experience. The edge computer also supports audio, USB and COM connections, making it easy to integrate with different controllers and audio systems to provide personalized gaming experiences.

It offers hassle-free maintenance as games and software can be easily installed and updated via USB.

Neu-X101 has various potential applications in the amusement machine market, including arcade machines to keep children entertained in toy stores while their parents shop, as well as in public places including airports and fast-food chains. It's also a great tool for educational purposes, offering games such as language teaching, drawing, and coloring. Additionally, the fanless Neu-X101 can be tailored to meet the specific needs of different customers, making it a dependable choice for amusement machine manufacturers seeking to create diverse gaming experiences for their customers.

With its versatility, advanced technology, and easy maintenance, Neu-X101 edge computer is an ideal choice for amusement machine manufacturers who are looking to create engaging and customized gaming experiences for their customers. As the industry continues to grow, NEXCOM is committed to providing innovative solutions that meet the evolving needs of the amusement machine market.



Neu-X101

- Intel® Apollo Lake J3455 processor
- Support 1 x RS232/422/485, 4 x USB, 2 x LAN, Audio-out
- Dual HDMI 4K@30Hz independent display
- Support power input 12V
- Palm size for IoT edge computer application



XPPC 16-200 Panel PC: the Dependable Choice for Dredging Equipment

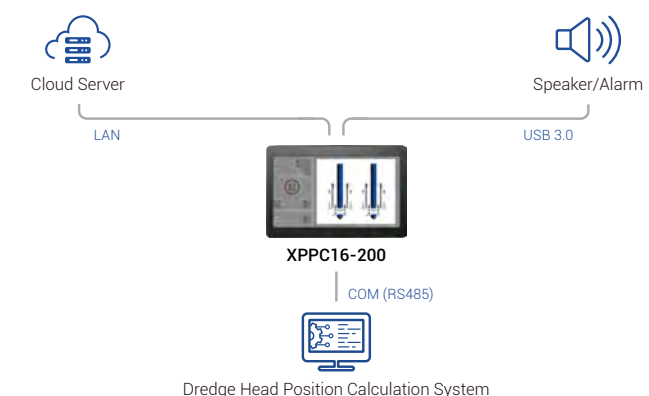
Water covers about 71% of the Earth's surface, enabling transportation and trade amongst distant cities and countries and providing a hospitable environment for aquatic flora and fauna. Over time, sedimentation naturally occurs, which may reduce the depths of waterways and threaten transportation and trade, as well as the health of plants and wildlife.

Luckily, dredging equipment can use suction tubes to remove this sediment, restoring a suitable environment for safe passage and flourishing habitation. However, this operation is not without challenges. Workers must carefully monitor the entire process, ensuring that the position of the suction tube is precise to effectively remove the sediment. Their equipment needs to have efficient and reliable display and data transmission capabilities, and it must continue to function stably even when exposed to dust and water splashes during operation. Moreover, the equipment must not only withstand harsh environmental conditions but also be capable of real-time data updates to ensure smooth operations.

One dredge operator turned to NEXCOM for a solution to help them flawlessly execute these tasks. NEXCOM proposed a powerful and efficient panel PC from among its distinguished industrial computers: the XPPC 16-200.

The XPPC 16-200 mitigated the threats of environmental damage with its thoughtful design, providing the reliability and stability that the dredge operator desperately needed. Its IP65 rating certifies high protection against dust and water splashes which dredging equipment is inevitably subject to. Optical bonding delivers readability in environments with high moisture concentrations. Furthermore, the panel PC offers durability and easy cleaning with its fully sealed construction and glass surface treatment. Such a design not only extends the device's lifespan but also reduces maintenance needs, minimizing potential downtime caused by equipment failure or contamination. With its robust exterior and highly adaptive structure, this panel PC continues to perform exceptionally well in the toughest work environments, ensuring long-term operational stability for dredging operations.

To process and display real-time data from the suction tube, the XPPC 16-200 is onboard with an 11th Generation Intel® Core™ processor; the i5 model even offers the Intel® Iris® Xe graphics card for more vivid presentations. The system architecture also supplies the perfect assortment of I/Os for the client's needs – one COM (RS485) for the dredge suction tube calculator, one USB for the alarm system, and one LAN for data transmission and management – once again proving that NEXCOM has the right fit for each of its valuable clients' requirements.


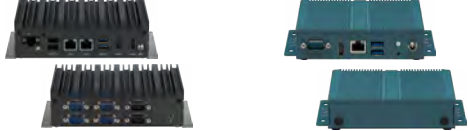




XPPC 16-200

- 15.6" TFT FHD 16:9 panel
- 10 Points P-Cap multi-touch with slim bezel design
- IP65 protection on the front
- Support: VESA/panel/open frame mount
- 11th Generation Intel® Tiger Lake-UP3 Core™ processor SoC
- 1 x DDR4 SO-DIMM up to 32G
- M.2 2280 Key M (PCIe x4) for storage device
- Onboard M.2 2230 Key E for optional Wi-Fi









Edge Computing System

Model				
	Neu-X100	Neu-X101	Neu-X101-6C-DC	Neu-X60
CPU	Intel® Apollo Lake N3350/N4200/J3455 (6W, 10W SoC)	Intel® Apollo Lake J3455 (10W SoC)	Intel® Apollo Lake J3455 (10W SoC)	Intel® Alder Lake N50 (6W SoC)
Chipset	-	-	-	-
Graphics	Intel® HD Graphics 505 Intel® HD Graphics 500	Intel® HD Graphics 500	Intel® HD Graphics 500	Intel® UHD Graphics
Memory	1 x DDR3L SO-DIMM 8GB Max.	1 x DDR3L SO-DIMM 8GB Max.	1 x DDR3L SO-DIMM 8GB Max.	1 x DDR4 SO-DIMM 16GB Max. Pre-installed with one 4G DDR4 memory in system
Gigabit LAN	2	2	2	1
WLAN	Optional	Optional	-	Optional
Hard Disk Interface	-	-	-	-
Flash Storage	1 x M.2 Key M 2242 (SATA3.0)	1 x M.2 Key M 2242 (SATA3.0)	1 x M.2 Key M 2242 (SATA3.0)	1 x M.2 Key M 2242 (SATA3.0/PCIe3.0 x4) Pre-installed with one M.2 Key M 128G SSD in system
Display Output	2 x HDMI2.0	2 x HDMI1.4b	2 x HDMI1.4b	1 x HDMI2.0
Display Resolution Max.	4096 x 2160 60Hz	3840 x 2160 30Hz	3840 x 2160 30Hz	3840 x 2160 30Hz
Output Channel	2 independent or clone	2 independent or clone	2 independent or clone	1
Video Capability (Hardware Decode)	HEVC (H.265), H.264, MVC, VP8, VP9, MPEG2, VC-1, WMV9, JPEG/ MJPEG	HEVC (H.265), H.264, MVC, VP8, VP9, MPEG2, VC-1, WMV9, JPEG/ MJPEG	HEVC (H.265), H.264, MVC, VP8, VP9, MPEG2, VC-1, WMV9, JPEG/ MJPEG	Accelerate up to 4K60 (8b AVC, 10b HEVC/VP9, SCC, AV1)
Audio Output	1 x Line-out (Internal) 1 x Mic-in (Internal) 1 x Speaker (Internal)	1 x Line-out (Internal) 1 x Mic-in (Internal) 1 x Speaker (Internal)	1 x Line-out (Internal) 1 x Mic-in (Internal) 1 x Speaker (Internal)	1 x Line-out (reserve) 1 x Mic-in (reserve) 1 x Speaker (reserve)
COM Port	1 x RS232/422/485 1 x RS232 (Internal)	1 x RS232/422/485 1 x RS232 (Internal)	1 x RS232/422/485 1 x RS232 4 x RS485	1 x RS232/422/485 1 x RS232 (Internal)
USB 2.0	4 (Internal)	2 (Edge) 2 (Internal)	2 (Edge) 2 (Internal)	2 (Internal)
USB3	2	2	2	2
Expansion Slot	1 x mini-PCIe (SIM Socket)	1 x mini-PCIe (SIM Socket)	-	1 x mini-PCIe (SIM Socket)
Operating Temp.	-5°C to 50°C	-5°C to 50°C	-5°C to 50°C	0°C to 40°C
DC Input	19V DC incl. AC/DC power adapter	12V DC incl. AC/DC power adapter	9~24V DC	12V DC incl. AC/DC power adapter
Dimension W x D x H (mm)	179.5 x 106 x 37	179.5 x 106 x 37	179 x 121 x 44	156 x 119.6 x 31
OS Support	Win10/Linux	Win10/Linux	Win10/Linux	Win10/Linux
Gross Weight (kg)	1.48	1.5	1.48	1.32
Certification	CE, FCC class A	CE, FCC class A	CE, FCC class A	CE, FCC class A

Model				
	Neu-X102-N50	Neu-X102-N97	Neu-X102-i3	Neu-X104
CPU	Intel® Alder Lake N50 (6W SoC)	Intel® Alder Lake N97 (12W SoC)	Intel® Alder Lake i3 N305 (15W SoC)	Intel® Twin Lake N150/N250/ N355 (6W, 15W SoC)
Chipset	-	-	-	-
Graphics	Intel® UHD Graphics	Intel® UHD Graphics	Intel® UHD Graphics	Intel® Graphics up to 32EU w/ INT8 extension
Memory	1 x DDR4 SO-DIMM 16GB Max.	1 x DDR4 SO-DIMM 16GB Max.	1 x DDR4 SO-DIMM 16GB Max.	1 x DDR4 SO-DIMM 32GB Max.
Gigabit LAN	2	2	2	2
WLAN	Optional	Optional	Optional	Optional
Hard Disk Interface	-	-	-	-
Flash Storage	1 x M.2 Key M 2242 (SATA3.0/PCIe3.0 x1)	1 x M.2 Key M 2242 (SATA3.0/PCIe3.0 x1)	1 x M.2 Key M 2242 (SATA3.0/PCIe3.0 x1)	1 x M.2 Key M 2242 (SATA3.0/PCIe3.0 x1)
Display Output	2 x HDMI2.0 1 x eDP/ LVDS (Internal)	2 x HDMI2.0 1 x eDP/ LVDS (Internal)	2 x HDMI2.0 1 x eDP/ LVDS (Internal)	2 x HDMI2.0 1 x eDP/ LVDS (Internal)
Display Resolution Max.	3840 x 2160 60Hz	3840 x 2160 60Hz	3840 x 2160 60Hz	3840 x 2160 60Hz
Output Channel	2 independent or clone	2 independent or clone	2 independent or clone	2 independent or clone
Video Capability (Hardware Decode)	Accelerate up to 4K60 (8b AVC, 10b HEVC/VP9, SCC, AV1)	Accelerate up to 4K60 (8b AVC, 10b HEVC/VP9, SCC, AV1)	Accelerate up to 4K60 (8b AVC, 10b HEVC/VP9, SCC, AV1)	Accelerate up to 4K60 (8b AVC, 10b HEVC/VP9, SCC, AV1)
Audio Output	1 x Line-out (Internal) 1 x Mic-in (Internal) 1 x Speaker (Internal)	1 x Line-out (Internal) 1 x Mic-in (Internal) 1 x Speaker (Internal)	1 x Line-out (Internal) 1 x Mic-in (Internal) 1 x Speaker (Internal)	1 x Line-out (Internal) 1 x Mic-in (Internal) 1 x Speaker (Internal)
COM Port	1 x RS232/422/485 1 x RS232 (Internal)	1 x RS232/422/485 1 x RS232 (Internal)	1 x RS232/422/485 1 x RS232 (Internal)	1 x RS232/422/485 1 x RS232 (Internal)
USB 2.0	3 (Internal)	3 (Internal)	3 (Internal)	3 (Internal)
USB3	4	4	4	4
Expansion Slot	1 x mini-PCIe (SIM Socket)	1 x mini-PCIe (SIM Socket)	1 x mini-PCIe (SIM Socket)	1 x mini-PCIe (SIM Socket)
Operating Temp.	-5°C to 50°C	-5°C to 50°C	-5°C to 50°C	-5°C to 50°C
DC Input	12V DC incl. AC/DC power adapter	12V DC incl. AC/DC power adapter	12V DC incl. AC/DC power adapter	12V DC incl. AC/DC power adapter
Dimension W x D x H (mm)	179.5 x 106 x 37	203.5 x 106 x 40	203.5 x 106 x 40	179 x 106 x 37
OS Support	Win10/Win11/Linux	Win10/Win11/Linux	Win10/Win11/Linux	Win10/Win11/Linux
Gross Weight (kg)	1.5	1.6	1.6	1.6
Certification	CE, FCC class B UL	CE, FCC class B UL	CE, FCC class A UL	CE, FCC class A


Edge Computing System


Model			
	Neu-X300	Neu-X300-F65	Neu-X302
CPU	9/8th Gen Intel® Core™ (Socket, 35W)	9/8th Gen Intel® Core™ (Socket, 65W)	9/8th Gen Intel® Core™ (Socket, 35W)
Chipset	Intel® PCH Q370/H310	Intel® PCH Q370	Intel® PCH Q370/H310
Graphics	Intel® UHD Graphics 630	Intel® UHD Graphics 630	Intel® UHD Graphics 630
Memory	2 x DDR4 SO-DIMM 32GB Max.	2 x DDR4 SO-DIMM 32GB Max.	2 x DDR4 SO-DIMM 32GB Max.
Gigabit LAN	2	2	2
WLAN	Optional	Optional	Optional
Hard Disk Interface	-	-	1 x 2.5" SATA
Flash Storage	1 x M.2 Key M 2280 (Q370, SATA3.0/PCIe3.0 x4) (H310, SATA3.0 only)	1 x M.2 Key M 2280 (SATA3.0/PCIe3.0 x4)	1 x M.2 Key B 2242/3042 (Q370: PCIe3.0 x 1/SATA3.0/USB3.0) (H310: SATA3.0 only, USB 2.0 if 3G/4G module not in use)
Display Output	3 x HDMI2.0 (Q370) 2 x HDMI2.0 (H310)	3 x HDMI2.0 (Q370)	1 x VGA 1 x HDMI1.4 1 x LVDS (Internal)
Display Resolution Max.	4096 x2160 60Hz	4096 x2160 60Hz	4096 x 2160 30Hz
Output Channel	3 independent or clone	3 independent or clone	2 independent or clone
Video Capability (Hardware Decode)	MPEG-2 (H.262), MPEG-4 (H.264), JPEG/ MJPEG, HEVC (H.265), VC-1, VP8, VP9	MPEG-2 (H.262), MPEG-4 (H.264), JPEG/ MJPEG, HEVC (H.265), VC-1, VP8, VP9	MPEG-2 (H.262), MPEG-4 (H.264), JPEG/ MJPEG, HEVC (H.265), VC-1, VP8, VP9
Audio Output	1 x Line-out 1 x Mic-in (Internal)	1 x Line-out 1 x Mic-in (Internal)	1 x Line-out 1 x Mic-in 1 x Speaker (Internal)
COM Port	1 x RS232/422/485 2 x RS232 (Internal)	1 x RS232/422/485 2 x RS232	3 x RS232/422/485 3 x RS232
USB 2.0	2 x for H310 (Internal) 4 x for Q370 (Internal)	6 (Edge) 4 (Internal)	6 (Internal, Q370) 3 (Internal, H310)
USB3	4	4	4
Expansion Slot	1 x M.2 Key E 2230	1 x M.2 Key E 2230	1 x M.2 Key E 2230
Operating Temp.	-5°C to 45°C	-5°C to 45°C	-5°C to 45°C
DC Input	12V DC incl. AC/DC power adapter	12V DC incl. AC/DC power adapter	12V DC incl. AC/DC power adapter
Dimension W x D x H (mm)	190 x 200 x 54.4	190 x 200 x 46.8	190 x 200 x 64.3
OS Support	Win10/Linux	Win10/Linux	Win10/Linux
Gross Weight (kg)	3.61	3	3.97
Certification	CE, FCC class A	CE, FCC class A	CE, FCC class A

Model			
	Neu-X303	Neu-X303mini	Neu-X304
CPU	12th Gen Intel® Core™ (Socket, 15W)	12th Gen Intel® Core™ (Socket, 45W)	14/13/12th Gen Intel® Core™ (Socket, 35W)
Chipset	-	-	Intel® PCH Q670E/H610E
Graphics	Intel® Iris® Xe Graphics (on i5/7) Intel® UHD Graphics 730 (on i3)	Intel® Iris® Xe Graphics (on i5/7) Intel® UHD Graphics 730 (on i3)	Intel® UHD Graphics 770
Memory	2 x DDR5 SO-DIMM 64GB Max.	2 x DDR5 SO-DIMM 64GB Max.	2 x DDR5 SO-DIMM 64GB Max.
Gigabit LAN	2	2	2
WLAN	Optional	Optional	Optional
Hard Disk Interface	-	-	-
Flash Storage	1 x M.2 Key M 2280 (PCIe3.0 x4)	1 x M.2 Key M 2280 (PCIe3.0 x4)	1 x M.2 Key M 2280 (SATA3.0/PCIe4.0 x4)
Display Output	1 x HDMI2.1 1 x DP1.4 2 x DP1.4 thru USB-C	1 x HDMI2.1 1 x DP1.4 2 x DP1.4 thru USB-C	3 x HDMI2.0 1x LVDS (Internal)
Display Resolution Max.	7680 x 4320 60Hz	7680 x 4320 60Hz	4096 x 2160 60Hz
Output Channel	4 independent or clone	4 independent or clone	3 independent or clone
Video Capability (Hardware Decode)	8K60 12b 4:2:0 HEVC/VP9/SCC; 8K30 10b 4:2:0 AV1; 5K60 10b 4:4:4 HEVC/VP9/SCC; 4K60 8b 4:2:0 AVC	8K60 12b 4:2:0 HEVC/VP9/SCC; 8K30 10b 4:2:0 AV1; 5K60 10b 4:4:4 HEVC/VP9/SCC; 4K60 8b 4:2:0 AVC	8K60 12b 4:2:0 HEVC/VP9/SCC; 8K30 10b 4:2:0 AV1; 5K60 10b 4:4:4 HEVC/VP9/SCC; 4K60 8b 4:2:0 AVC
Audio Output	-	-	1 x Line-out 1 x Mic-in
COM Port	1 x RS232 (Internal)	1 x RS232 (Internal)	1 x RS232/422/485 1 x RS232
USB 2.0	1 (Internal)	1 (Internal)	4 (Edge, Q670E) 5 (Edge, H610E)
USB3	6 (2 thru USB type C)	6 (2 thru USB type C)	4 (Edge, Q670E) 3 (Edge, H610E)
Expansion Slot	1 x M.2 Key E 2230	1 x M.2 Key E 2230	1 x M.2 Key E 2230 1 x M.2 Key B 2242/3042/3052
Operating Temp.	0°C to 50°C	0°C to 60°C	-5°C to 45°C
DC Input	12V DC incl. AC/DC power adapter	12V DC incl. AC/DC power adapter	12-24V DC (Q670E) 12V DC (H610E) incl. AC/DC power adapter
Dimension W x D x H (mm)	190 x 150 x 59.8	183 x 137.9 x 47.9	210 x 210 x 50
OS Support	Win10/Linux	Win10/Linux	Win10/Win11/Linux
Gross Weight (kg)	3.05	3.25	3.9
Certification	CE, FCC class A	CE, FCC class A	CE, FCC class A



NEW


Visual Edge Computer

Model					
	NDiS B560-Q	NDiS B561	NDiS B561-PoE	NDiS B561-H	NDiS B561S
CPU	9/8th Gen Intel® Core™ (Socket, 35W)	14/13/12th Gen Intel® Core™ (Socket, 35W)	14/13/12th Gen Intel® Core™ (Socket, 35W)	9/8th Gen Intel® Core™ (Socket, 35W)	14/13/12th Gen Intel® Core™ (Socket, 35W)
Chipset	Intel® PCH Q370	Intel® PCH Q670E	Intel® PCH Q670E	Intel® PCH H310	Intel® PCH H610E
Graphics	Intel® UHD Graphics 630	Intel® UHD Graphics	Intel® UHD Graphics	Intel® UHD Graphics 630	Intel® UHD Graphics
Memory	2 x DDR4 SO-DIMM 32GB Max.	2 x DDR5 SO-DIMM 64GB Max.	2 x DDR5 SO-DIMM 64GB Max.	2 x DDR5 SO-DIMM 32GB Max.	2 x DDR5 SO-DIMM 64GB Max.
Gigabit LAN	2	3	3 (LAN 2/3 support PoE function)	2	2
WLAN	Optional	Optional	Optional	Optional	Optional
Hard Disk Interface	1x2.5" SATA	-	-	1x2.5" SATA	-
Flash Storage	1 x M.2 Key M 2280 (SATA3.0/PCIe3.0 x4)	1 x M.2 Key M 2280 (PCIe4.0 x4) 1 x M.2 Key M 2280 (SATA3.0)	1 x M.2 Key M 2280 (PCIe4.0 x4) 1 x M.2 Key M 2280 (SATA3.0)	1 x M.2 Key M 2280 (SATA3.0)	1 x M.2 Key M 2280 (PCIe4.0 x4) 1 x M.2 Key M 2280 (SATA3.0)
Display Output	3 x HDMI2.0	1 x HDMI2.1 2 x HDMI2.0	1 x HDMI2.1 2 x HDMI2.0	2 x HDMI2.0	2 x HDMI2.0
Display Resolution Max.	HDMI2.0: 4096 x 2160 60Hz	HDMI2.1: 7680 x 4320 60Hz HDMI2.0: 4096 x 2160 60Hz	HDMI2.1: 7680 x 4320 60Hz HDMI2.0: 4096 x 2160 60Hz	HDMI2.0:4096 x 2160 60Hz	4096 x 2160 60Hz
Output Channel	3 independent or clone	3 independent or clone	3 independent or clone	2 independent or clone	2 independent or clone
Video Capability (Hardware Decode)	MPEG-2 (H.262), MPEG-4(H.264), JPEG/MJPEG, HEVC(H.265), VC-1, VP8, VP9	8K60 12b 4:2:0 HEVC/VP9/SCC 8K30 10b 4:2:0 AV1 5K60 10b 4:4:4 HEVC/VP9/SCC 4K60 8b 4:2:0 AVC	8K60 12b 4:2:0 HEVC/VP9/SCC 8K30 10b 4:2:0 AV1 5K60 10b 4:4:4 HEVC/VP9/SCC 4K60 8b 4:2:0 AVC	MPEG-2 (H.262), MPEG-4(H.264), JPEG/MJPEG, HEVC(H.265), VC-1, VP8, VP9	8K60 12b 4:2:0 HEVC/VP9/SCC 8K30 10b 4:2:0 AV1 5K60 10b 4:4:4 HEVC/VP9/SCC 4K60 8b 4:2:0 AVC
Audio Output	1 x Line-out 1 x Mic-in	1 x Line-out 1 x Mic-in 1 x Speaker (Internal)	1 x Line-out 1 x Mic-in 1 x Speaker (Internal)	1 x Line-out 1 x Mic-in	1 x Line-out 1 x Mic-in 1 x Speaker (Internal)
COM Port	1 x RS232/422/485 3 x RS232	1 x RS232/422/485 3 x RS232	1 x RS232/422/485 3 x RS232	1 x RS232/422/485 3 x RS232	1 x RS232/422/485 3 x RS232
USB 2.0	-	4 (Internal)	4 (Internal)	2	4
USB3	6	8	8	4	2
Expansion Slot	1 x M.2 Key M 2280 1 x M.2 Key E 2230 1 x M.2 Key B 2242/3042/3052	2 x M.2 Key M 2280 1 x M.2 Key E 2230 1 x M.2 Key B 2242/3042/3052	2 x M.2 Key M 2280 1 x M.2 Key E 2230 1 x M.2 Key B 2242/3042/3052	1 x M.2 Key M 2280 1 x M.2 Key E 2230 1 x M.2 Key B 2242/3042/3052	2 x M.2 Key M 2280 1 x M.2 Key E 2230 1 x M.2 Key B 2242/3042/3052
Operating Temp.	-20°C to 60°C	-20°C to 60°C	0°C to 40°C	0°C to 40°C	0°C to 50°C
DC Input	12V DC incl. AC/DC power adapter	12-24V DC incl. AC/DC power adapter	24V DC incl. AC/DC power adapter	12V DC incl. AC/DC power adapter	12V DC incl. AC/DC power adapter
Dimension W x D x H (mm)	238 x 192 x 67.3	238 x 192 x 67.3	238 x 192 x 67.3	238 x 192 x 39	238 x 192 x 39
OS Support	Win10/Linux	Win10/11/Linux	Win10/11/Linux	Win10/Linux	Win10/11/Linux
Gross Weight (kg)	5	4.9	4.9	4	3.9
Certification	CE, FCC class A	CE, FCC class A	CE, FCC class A	CE, FCC class A	CE, FCC class A

Model				
	NDiS B360	NDiS B362	NDiS B361	NDiS B363
CPU	Intel® Core i5-1145G7E Intel® Core i3-1115G4E (15W, SoC)	Intel Core Ultra 7 165U Intel Core Ultra 7 155U Intel Core Ultra 5 135U Intel Core Ultra 5 125U (15W, SoC)	13th Gen Intel® Core™ i7-1365UE 13th Gen Intel® Core™ i5-1345UE 13th Gen Intel® Core™ i5-1335UE 13th Gen Intel® Core™ i3-1315UE (15W, SoC)	Intel Core Ultra 7 265U Intel Core Ultra 7 255U Intel Core Ultra 5 235U Intel Core Ultra 5 225U (15W, SoC)
Chipset	-	-	-	-
Graphics	Intel® Iris® Xe Graphics (on i5) Intel® UHD Graphics (on i3)	Intel® Graphics	Intel® Iris® Xe LPG Graphics (on i7, i5) Intel® UHD Graphics (on i3)	Intel® Iris® Xe LPG Graphics
Memory	1 x DDR4 SO-DIMM 32GB Max.	2 x DDR5 SO-DIMM 96GB Max.	2 x DDR5 SO-DIMM 96GB Max.	2 x DDR5 SO-DIMM 96GB Max.
Gigabit LAN	2	2	2	2
WLAN	Optional	Optional	Optional	Optional
Hard Disk Interface	-	-	-	-
Flash Storage	1 x M.2 Key M 2280 (PCIe3.0 x4)	1 x M.2 Key M 2280 (PCIe4.0 x4)	1 x M.2 Key M 2280 (SATA3.0/PCIe3.0 x4)	1 x M.2 Key M 2280 (PCIe4.0 x4)
Display Output	1 x DP++ 1 x HDMI2.0	2 x HDMI2.0	2 x HDMI2.0	2 x HDMI2.0
Display Resolution Max.	HDMI2.0: 4096 x 2160 60Hz DP++: 4096 x 2304 60Hz	4096 x 2160 60Hz	4096x2160 60Hz	4096 x 2160 60 Hz
Output Channel	2 independent or clone	2 independent or clone	2 independent or clone	2 independent or clone
Video Capability (Hardware Decode)	AV1, VP9 8/10/12bit, H.265/HEVC 8/10/12 bit, H.264/AVC, MPEG2	8K60 12b 4:2:0 HEVC/VP9/SCC 8K30 10b 4:2:0 AV1 5K60 10b 4:4:4 HEVC/VP9/SCC 4K60 8b 4:2:0 AVC	8K60 12b 4:2:0 HEVC/VP9/SCC 8K30 10b 4:2:0 AV1 5K60 10b 4:4:4 HEVC/VP9/SCC 4K60 8b 4:2:0 AVC	8K60 12b 4:2:0 HEVC/VP9/SCC 8K30 10b 4:2:0 AV1 5K60 10b 4:4:4 HEVC/VP9/SCC 4K60 8b 4:2:0 AVC
Audio Output	1 x Line-out 1 x Mic-in (Internal) 1 x Speaker (Internal)	1 x Line-out 1 x Mic-in (Internal) 1 x Speaker (Internal)	1 x Line-out 1 x Mic-in (Internal) 1 x Speaker out (Internal)	1 x Line-out 1 x Mic-in (Internal) 1 x Speaker (Internal)
COM Port	1 x RS232/422/485 1 x RS232	2 x RS232/422/485	2 x RS232/422/485	1 x RS232/422/485 1 x RS232
USB 2.0	4 (Internal)	3 (External) 4 (Internal)	3 (External) 2 (Internal)	3 (External) 4 (Internal)
USB3	4	1	1	1
Expansion Slot	1 x M.2 Key E 2230	1 x M.2 Key E 2230 1 x M.2 Key B 2242/3042/3052	2 x M.2 Key M 2280 1 x M.2 Key E 2230 1 x M.2 Key B 2242/3042/3052	1 x M.2 Key E 2230 1 x M.2 Key B 2242/3042/3052
Operating Temp.	-20°C to 60°C	0°C to 60°C	-20 °C to 60°C	0°C to 60°C
DC Input	12V DC incl. AC/DC power adapter	12V DC incl. AC/DC power adapter	12-24V DC	12-24V DC
Dimension W x D x H (mm)	200 x 132.6 x 36	200 x140 x37	200 x 140 x 37	200 x140 x 37
OS Support	Win10/11/Linux	Win10/11/Linux	Win10/11/Linux	Win10/11/Linux
Gross Weight (kg)	2	2.54	2.54	2.54
Certification	CE, FCC class A UL	CE, FCC class A	CE, FCC class A	CE, FCC class A

Visual Edge Computer

Model				
	NDiS B337	NDiS B338	NDiS B339	NDiS B116
CPU	Intel® Apollo Lake J3455 (10W, SoC)	Intel® Apollo Lake J6412 (10W, SoC)	Intel® Amston Lake X7211RE/ X7433RE (6W,9W SoC)	Rockchip RK3399
Chipset	-	-	-	-
Graphics	Intel® HD 500 Graphics	Intel® UHD Graphics	Intel® UHD Graphics	Mali-T864 (Embedded)
Memory	1 x DDR3L SO-DIMM 8GB Max.	2 x DDR4 SO-DIMM 32GB Max.	1 x DDR4 SO-DIMM 16GB Max.	DDR4 2GB on-board
Gigabit LAN	2	2	2	2
WLAN	Optional	Optional	Optional	Optional
Hard Disk Interface	-	-	-	-
Flash Storage	M.2 Key M 2242 (SATA3.0)	1 x M.2 Key M 2280 (PCIe3.0 x4)	1 x M.2 Key M 2242 (PCIe3.0 x1/SATA3.0)	eMMC 8GB on-board
Display Output	2 x HDMI1.4	3 x HDMI2.0	2 x HDMI1.4	1 x HDMI1.4 1 x HDMI2.0
Display Resolution Max.	3840 x 2160 30Hz	4096 x 2160 60Hz	3840 x 2160 30Hz	3840x2160 4096x2160 (single display)
Output Channel	2 independent or clone	3 independent or clone	2 independent or clone	2 clone
Video Capability (Hardware Decode)	HEVC (H.265), H.264, MVC, VP8, VP9, MPEG2, VC-1, WMV9, JPEG/MJPEG	H.264/AVC, MPEG-2, VC-1, JPEG/MJPEG VP8, VP9, HEVC 8, 10-bit	Video decode hardware acceleration up to 4K@60	MPEG-1, MPEG-2, MPEG-4, H.263, H.264, AVS, VC-1, VP8, MVC, HEVC/H.265
Audio Output	1 x Line-out 1 x Mic-in (Internal) 1 x Speaker (Internal)	1 x Line-out 1 x Mic-in 1 x Speaker (Internal)	1 x Line-out (Internal) 1 x Mic-in (Internal) 1 x Speaker (Internal)	1 x Line-out (Internal) 1 x Mic-in (Internal) 1 x Speaker (Internal)
COM Port	1 x RS232/422/485 1 x RS232	1 x RS232/422/485 3 x RS232	1 x RS232/422/485 1 x RS232	1 x RS232/422/485
USB 2.0	2 2 (Internal)	5	3 (Internal)	1
USB3	2	1	4	1
Expansion Slot	1 x mini-PCIe	1 x mini-PCIe 1 x M.2 Key B 2242/3042/3052	1 x mini-PCIe (SIM Socket)	1 x mini-PCIe
Operating Temp.	-20°C to 60°C	-20°C to 60°C	-20°C to 60°C	-20°C to 60°C
DC Input	12V DC incl. AC/DC power adapter	12-24V DC incl. AC/DC power adapter	12-24V DC	12V DC incl. AC/DC power adapter
Dimension W x D x H (mm)	200 x 117.6 x 40	200 x 152.6 x 39.8	224 x 150 x 39.8 (with mount bracket)	179.5 x 112.5 x 39.5
OS Support	Win10/Linux	Win10	Win10/11/Linux	Android 7.1
Gross Weight (kg)	2	2	2	3.32
Certification	CE, FCC class A	CE, FCC class A UL	CE, FCC class A	CE, FCC class A



Model		
	NDiS V1000	NDiS V1100
CPU	AMD Ryzen V1605B Quad Core	Intel® Core i7-1185G7E Intel® Core i5-1145G7E Intel® Core i3-1115G4E
Chipset	-	-
Graphics	AMD Radeon Vega 8	Intel® Iris® Xe Graphics (on i5/i7) Intel® UHD Graphics for 11th Gen Intel® Processors (on i3)
Memory	2 x DDR4 SO-DIMM 32GB Max.	2 x DDR4 SO-DIMM 64GB Max.
Gigabit LAN	2	2
WLAN	-	-
Hard Disk Interface	-	-
Flash Storage	1 x M.2 Key M 2242/2280 (SATA3.0)	1 x M.2 Key M 2280 (SATA3.0/PCIe3.0 x4)
Display Output	4 x HDMI2.0	4 x HDMI2.0
Display Resolution Max.	4096 x 2160 60Hz	4096 x 2160 60Hz
Output Channel	4 independent, Expanded or Clone	4 independent, Expanded or Clone
Video Capability (Hardware Decode)	H.264, H.265 / HEVC (8 bit), H.265 / HEVC (10 bit), VP8, VP9, VC-1, AVC, JPEG	5K60 10b 4:4:4 HEVC/VP9/SCC 8K60 12b 4:2:0 HEVC/VP9/SCC 8K30 10b 4:2:0 AV11 4K60 8b 4:2:0 AVC
Audio Output	1 x MIC-in 1 x Line-out (Internal)	1 x MIC-in 1 x Line-out
COM Port	1 x RS232/422/485 3 x RS232 (Internal)	1 x RS232/422/485 1 x RS232
USB 2.0	2 (Internal)	1
USB3	4	3
Expansion Slot	1 x M.2 Key E 2230	1 x mini-PCIe 1 x M.2 Key B 2242/3042/3052
Operating Temp.	0°C to 40°C	0°C to 45°C
DC Input	12V DC incl. AC/DC power adapter	12V DC incl. AC/DC power adapter
Dimension W x D x H (mm)	190 x 200 x 54.4	190 x 165 x 51.1
OS Support	Win10/Linux	Win10/11/Linux
Gross Weight (kg)	3.29	2.84
Certification	CE, FCC class A	CE, FCC class A

Embedded Touchscreen Computer





Model				
	XPPC10-100	XPPC16-101	XPPC22-100A	XPPC24-100A
Indoor				
CPU	Intel® Apollo Lake® J3455 (10W, SoC)	Intel® Apollo Lake® J3455 (10W, SoC)	Intel® Apollo Lake® J3455 (10W, SoC)	Intel® Apollo Lake® J3455 (10W, SoC)
LCD Size	10.1", 16:10	15.6", 16:9	21.5", 16:9	23.8", 16:9
Max Resolution	WXGA, 1280 x 800	FHD, 1920 x1080	FHD, 1920 x1080	FHD, 1920 x1080
Touch Screen	10 Point P-Cap	10 Point P-Cap	10 Point P-Cap	10 Point P-Cap
Surface Treatment	AF	AF	AF	AF
Touch Light Transmission	90%	90%	85%	85%
Luminace (cd/m2)	Panel: 400 XPPC Touch: 90% of panel's luminance after optical bonding	Panel: 450 XPPC Touch: 90% of panel's luminance after optical bonding	Panel: 400 XPPC Touch: 85% of panel's luminance after optical bonding	Panel: 350 XPPC Touch: 85% of panel's luminance after optical bonding
Contrast Ratio	800:1	1000: 1	1000: 1	1000: 1
LCD Color	16.7M	16.7M	16.7M	16.7M
Viewing Angle	89 (U), 89 (D), 89 (L), 89 (R)	89 (U), 89 (D), 89 (L), 89 (R)	89 (U), 89 (D), 89 (L), 89 (R)	89 (U), 89 (D), 89 (L), 89 (R)
Backlight	LED	LED	LED	LED
Memory	1 x DDR3L SO-DIMM 8GB Max.	1 x DDR3L SO-DIMM 8GB Max.	1 x DDR3L SO-DIMM 8GB Max.	1 x DDR3L SO-DIMM 8GB Max.
Storage	1 x M.2 Key M 2242 (SATA3.0)	1 x M.2 Key M 2242 (SATA3.0)	1 x M.2 Key M 2242 (SATA3.0)	1 x M.2 Key M 2242 (SATA3.0)
2nd Display	1 x HDMI2.0	1 x HDMI1.4	1 x HDMI2.0	1 x HDMI2.0
Gigabit LAN	2	2	2	2
USB3	2	2	2	2
USB2.0	-	2	-	-
COM Port	1 x RS232/422/485	1 x RS232/422/485	1 x RS232/422/485	1 x RS232/422/485
Audio Output	1 x Line-out	1 x Line-out	1 x Line-out	1 x Line-out
Expansion	1 x mini-PCle (SIM Socket)	1 x mini-PCle (SIM Socket)	1 x mini-PCle (SIM Socket)	1 x mini-PCle (SIM Socket)
Housing Material	Metal	Metal	Metal	Metal
Mounting	VESA 75 x 75mm Panel Mount (Optional kit) Open Frame (Optional kit)	VESA 100 x100mm Panel Mount (Optional kit) Open Frame (Optional kit)	VESA 100 x100mm Panel Mount (Optional kit) Open Frame (Optional kit)	VESA 100 x100mm Panel Mount (Optional kit) Open Frame (Optional kit)
Power Input	12V DC	19V DC	19V DC	19V DC
Power Adapter	60W AC/DC power adapter with lock type	90W AC/DC power adapter with lock type	90W AC/DC power adapter with lock type	90W AC/DC power adapter with lock type
Operating Temp.	0°C to 50°C	0°C to 50°C	0°C to 50°C	0°C to 50°C
Storage Temp.	-20°C to 60°C	-20°C to 60°C	-20°C to 60°C	-20°C to 60°C
Operating Humidity	10%~90% Non-condensing	10%~90% Non-condensing	10%~90% Non-condensing	10%~90% Non-condensing
IP level	IP65 on the Front	IP65 on the Front	IP65 on the Front	IP65 on the Front
Cut-Out size (W x H) (mm)	246.5 x 164.5 (Horizontal)	370.5 x 240 (Horizontal)	508.4 x 303.4 (Horizontal)	546.7 x 326.1 (Horizontal)
Dimensionn (W x H x D) (mm)	260.3 x 178.3 x 44.7 (Horizontal)	382.2 x 251.4 x 51.9 (Horizontal)	520.6 x 315.6 x 54 (Horizontal)	557 x 336.7 x 55 (Horizontal)
OS Support	Win10/Linux	Win10/Linux	Win10/Linux	Win10/Linux
Gross Weight(Kg)	3	4.7	7.5	8.5
Certification	CE, FCC class A UL	CE, FCC class A	CE, FCC class A	CE, FCC class A

Model					
	XPPC10-200	XPPC16-200	XPPC24-200A	XPPC10-10N97	XPPC16-10N97
Indoor					
CPU	Intel® Core i5-1145G7E Intel® Core i3-1115G4E (15W, SoC)	Intel® Core i5-1145G7E Intel® Core i3-1115G4E (15W, SoC)	Intel® Core i5-1145G7E Intel® Core i3-1115G4E (15W, SoC)	Intel® Alder Lake N97 (12W, SoC)	Intel® Alder Lake N97 (12W, SoC)
LCD Size	10.1", 16:10	15.6", 16:9	23.8", 16:9	10.1", 16:10	15.6", 16:9
Max Resolution	WXGA, 1280 x 800	FHD, 1920 x1080	FHD, 1920 x1080	WXGA, 1280 x 800	FHD, 1920 x1080
Touch Screen	10 Point P-Cap	10 Point P-Cap	10 Point P-Cap	10 Point P-Cap	10 Point P-Cap
Surface Treatment	AF	AF	AF	AF	AF
Touch Light Transmission	90%	90%	85%	90%	90%
Luminace (cd/m2)	Panel: 400 XPPC Touch: 90% of panel's luminance after optical bonding	Panel: 450 XPPC Touch: 90% of panel's luminance after optical bonding	Panel: 350 XPPC Touch: 85% of panel's luminance after air bonding	Panel: 400 XPPC Touch: 90% of panel's luminance after optical bonding	Panel: 450 XPPC Touch: 90% of panel's luminance after optical bonding
Contrast Ratio	800:1	1000: 1	1000: 1	800: 1	1000: 1
LCD Color	16.7M	16.7M	16.7M	16.7M	16.7M
Viewing Angle	89 (U), 89 (D), 89 (L), 89 (R)	89 (U), 89 (D), 89 (L), 89 (R)	89 (U), 89 (D), 89 (L), 89 (R)	89 (U), 89 (D), 89 (L), 89 (R)	89 (U), 89 (D), 89 (L), 89 (R)
Backlight	LED	LED	LED	LED	LED
Memory	1 x DDR4 SO-DIMM 32GB Max.	1 x DDR4 SO-DIMM 32GB Max.	1 x DDR4 SO-DIMM 32GB Max.	1 x DDR4 SO-DIMM 16GB Max.	1 x DDR4 SO-DIMM 16GB Max.
Storage	1 x M.2 Key M 2280 (PCIe3.0 x4)	1 x M.2 Key M 2280 (PCIe3.0 x4)	1 x M.2 Key M 2280 (PCIe3.0 x4)	1 x M.2 Key M 2230/2242 (SATA3.0/PCIe3.0 x1)	1 x M.2 Key M 2230/2242 (SATA3.0/PCIe3.0 x1)
2nd Display	1 x HDMI2.0	1 x HDMI2.0 1 x DP++	1 x HDMI2.0 1 x DP++	1 x HDMI2.0	1 x HDMI2.0
Gigabit LAN	2	2	2	2	2
USB3	4	4	4	2	2
USB2.0	-	-	-	2	2
COM Port	1 x RS232/422/485	1 x RS232/422/485	1 x RS232/422/485	1 x RS232/422/485	1 x RS232/422/485
Audio Output	1 x Line-out	1 x Line-out	1 x Line-out	1 x Line-out	1 x Speaker
Expansion	1 x M.2 Key E 2230	1 x M.2 Key E 2230	1 x M.2 Key E 2230	1 x mini-PCle	1 x mini-PCle
Housing Material	Metal	Metal	Metal	Metal	Metal
Mounting	VESA 75 x 75mm Panel Mount (Optional kit) Open Frame (Optional kit)	VESA 100 x100mm Panel Mount (Optional kit) Open Frame (Optional kit)	VESA 100 x100mm Panel Mount (Optional kit) Open Frame (Optional kit)	VESA 100 x100mm Panel Mount (Optional kit) Open Frame (Optional kit)	VESA 100 x100mm Panel Mount (Optional kit) Open Frame (Optional kit)
Power Input	12V DC	12V DC	12V DC	12V DC	12V DC
Power Adapter	60W AC/DC power adapter with lock type	96W AC/DC power adapter with lock type	96W AC/DC power adapter with lock type	60W AC/DC power adapter with lock type	65W AC/DC power adapter with lock type
Operating Temp.	0°C to 50°C	0°C to 50°C	0°C to 50°C	0°C to 50°C	0°C to 50°C
Storage Temp.	-20°C to 60°C	-20°C to 60°C	-20°C to 60°C	-20°C to 60°C	-20°C to 60°C
Operating Humidity	10%~90% Non-condensing	10%~90% Non-condensing	10%~90% Non-condensing	10%~90% Non-condensing	10%~90% Non-condensing
IP level	IP65 on the Front	IP65 on the Front	IP65 on the Front	IP65 on the Front	IP65 on the Front
Cut-Out size (W x H) (mm)	246.5 x 164.5 (Horizontal)	370.5 x 240 (Horizontal)	557 x 326.1 (Horizontal)	246.5 x 164.5 (Horizontal)	270.5 x 240 (Horizontal)
Dimensionn (W x H x D) (mm)	260.3 x 178.3 x 50.4 (Horizontal)	382.2 x 251.4 x 51.9 (Horizontal)	557 x 336.7 x 55 (Horizontal)	260.3 x 178.3 x 47.9 (Horizontal)	368.9 x 251.4 x 51.8 (Horizontal)
OS Support	Win10/Linux	Win10/Linux	Win10/Linux	Win10/11/Linux	Win10/11/Linux
Gross Weight(Kg)	3	4.6	7.85	3	4.6
Certification	CE, FCC class A	CE, FCC class A	CE, FCC class A	CE, FCC class A	CE, FCC class A






Embedded Touchscreen Computer






Model		
	HPPC15-10X7211	HPPC12-10X7211
	Semi-Outdoor	
CPU	Intel® Amston Lake x 7211RE (6W, SoC)	
LCD Size	15", 4:3	12.1", 4:3
Max Resolution	XGA, 1024 x768	XGA, 1024 x768
Touch Screen	10 Point P-Cap Water protection	10 Point P-Cap Water protection
Surface Treatment	AF + AG Anti-IR & UV	AF + AG Anti-IR & UV
Touch Light Transmission	80%	80%
Luminance (cd/m2)	Panel: 1800 HPPC Touch: 80% of panel's luminance after optical bonding	Panel: 1300 HPPC Touch: 80% of panel's luminance after optical bonding
Contrast Ratio	2500 :1	1000 : 1
LCD Color	16.7M	16.7M
Viewing Angle	88 (U), 88 (D), 88 (L), 88 (R)	89 (U), 89 (D), 89 (L), 89 (R)
Backlight	LED	LED
Memory	1 x DDR4 SO-DIMM 16GB Max.	1 x DDR4 SO-DIMM 16GB Max.
Storage	1 x M.2 Key M 2230/2242 (SATA3.0/PCIe3.0 x1)	1 x M.2 Key M 2230/2242 (SATA3.0/PCIe3.0 x1)
2nd Display	1 x HDMI2.0	1 x HDMI2.0
Gigabit LAN	2	2
USB3	2	2
USB2.0	2	2
COM Port	1 x RS232/422/485 1 x RS-232 (Reserved)	1 x RS232/422/485 1 x RS-232 (Reserved)
Audio Output	1 x Line-out	1 x Line-out
Expansion	1 x mini-PCIe	1 x mini-PCIe
Housing Material	Metal	Metal
Mounting	VESA 100 x 100mm Panel Mount (Optional kit) Open Frame (Optional kit)	VESA 100 x 100mm Panel Mount (Optional kit) Open Frame (Optional kit)
Power Input	12-24V DC	12-24V DC
Power Adapter	NA	NA
Operating Temp.	-20°C to 60°C	-20°C to 60°C
Storage Temp.	-20°C to 80°C	-20°C to 80°C
Operating Humidity	10%~90% Non-condensing	10%~90% Non-condensing
IP level	IP65 on the Front	IP65 on the Front
Cut-Out size (W x H) (mm)	341.6 x 284.35 (Horizontal)	281.9 x 235.8 (Horizontal)
Dimension (W x H x D) (mm)	351.9 x 295.75 x 58.15 (Horizontal)	293.56 x 247.46 x 52.45 (Horizontal)
OS Support	Win10/11/Linux	Win10/11/Linux
Gross Weight(Kg)	5	4
Certification	CE, FCC class A	CE, FCC class A

Embedded Computing board


Model				
	X100	X101	X102	X103
Type	3.5"	3.5"	3.5"	3.5"
CPU	Intel® Apollo Lake N3350/J3455 (6W, 10W, SoC)	Intel® Apollo Lake J3455 (10W, SoC)	Intel® Alder Lake-N Series (SoC) N50/N97/N305 (6W, 12W, 15W SoC)	Intel® Elkhart Lake Series (SoC) x6211E/x6413E (6W, 9W SoC)
Chipset	-	-	-	-
Graphics	Intel® HD Graphics 500	Intel® HD Graphics 500	Intel® UHD Graphics	Intel® UHD Graphics
Memory	1 x DDR3L SO-DIMM 8GB Max.	1 x DDR3L SO-DIMM 8GB Max.	1 x DDR4 SO-DIMM 16GB Max.	1 x DDR4 SO-DIMM 32GB Max.
Gigabit LAN	2	2	2	3
WLAN	Optional	Optional	Optional	Optional
Hard Disk Interface	-	-	1 x 2.5" SATA	-
Flash Storage	1 x M.2 Key M 2242 (SATA3.0)	1 x M.2 Key M 2242 (SATA3.0)	1 x M.2 Key M 2242 (SATA3.0/PCIe3.0 x1)	1 x M.2 Key B 3052 (SATA3.0/USB2.0/USB3.0)
Display Output	1 x HDMI2.0 + LVDS (Internal) or 2 x HDMI2.0 + LVDS (Internal)	2 x HDMI1.4b 1 x eDP (optional: LVDS, Internal)	2 x HDMI2.0 1 x eDP (optional LVDS, Internal)	1 x HDMI1.4 1 x LVDS (Internal)
Display Resolution Max.	3840 x 2160 60Hz	3840 x 2160 30Hz	3840 x 2160 30Hz	3840 x 2160 30Hz
Video Capability (Hardware Decode)	HEVC (H.265), H.264, MVC, VP8, VP9, MPEG2, VC-1, WMV9, JPEG/ MJPEG	HEVC (H.265), H.264, MVC, VP8, VP9, MPEG2, VC-1, WMV9, JPEG/ MJPEG	Accelerate up to 4K60 (8b AVC, 10b HEVC/VP9, SCC, AV1)	H.264/AVC, MPEG-2, VC-1, JPEG/MJPEG VP8, VP9, HEVC 8, 10-bit
Audio Output	1 x Line-out (Internal)	1 x Line-out (Internal) 1 x Mic-in (Internal) 1 x Speaker (Internal)	1 x Line-out (Internal) 1 x Mic-in (Internal) 1 x Speaker (Internal)	1 x Line-out (Internal) 1 x Mic-in (Internal) 1 x Speaker (Internal)
COM Port	1 x RS232/422/485 1 x RS232 (Internal)	1 x RS232/422/485 (Internal) 1 x RS232 (Internal)	1 x RS232/422/485 1 x RS232 (Internal)	2 x RS232/422/485 4 x RS232 (Internal)
USB 2.0	4 (Internal)	2 (Edge) 2 (Internal)	2 (Internal)	4 (Internal)
USB3	2	2	4	4
Expansion Slot	1 x mini-PCIe (PCIe2.0/USB2.0/SATA3.0)	1 x mini-PCIe (PCIe2.0/USB2.0/SATA3.0)	1 x mini-PCIe (PCIe3.0/USB2.0)	1 x mini-PCIe (PCIe or SATA3.0/USB2.0) 1 x M.2 Key E 2230 1 x M.2 Key B 3052 (SATA3.0/USB3.0/USB2.0)
SIM socket	v	v	v	v
Operating Temp.	0°C to 60°C	0°C to 60°C	0°C to 60°C	-40°C to 85°C
DC Input	12/19VDC	12/19VDC	12V DC	12-24V DC
Dimension W x D x H (mm)	146 x 102	146 x 102	146 x 102	146 x 102
OS Support	Win10/Linux	Win10/Linux	Win10/11/Linux	Win10/11/Linux
Certification	CE, FCC class A	CE, FCC class A	CE, FCC class A	CE, FCC class A

Embedded Computing board

Model					
	X200	X201	X202	X203	X303
Type	3.5"	3.5"	3.5"	3.5"	3.5"
CPU	11th Gen Intel® Core™ (15W, SoC)	Intel® Meteor Lake Core Ultra U Processor (15W, SoC)	14th Gen Intel® Core™ (15W, SoC)	Intel® Arrow Lake Core Ultra U Processor (15W, SoC)	12th Gen Intel® Core™ (45/15W, Socket)
Chipset	-	-	-	-	-
Graphics	Intel® HD 630 Graphics on i3 Intel® Iris® Xe Graphics on i5	Intel® Xe LPG graphics	Intel® Xe LPG graphics	Intel® Xe LPG graphics	
Memory	1 x DDR4 SO-DIMM 32GB Max.	2 x DDR5 SO-DIMM 96GB Max.	2 x DDR5 SO-DIMM 96GB Max.	2 x DDR5 SO-DIMM 96GB Max.	2x DDR5 SO-DIMM 64GB Max.
Gigabit LAN	2	2	2	2	3
WLAN	Optional	Optional	Optional	Optional	Optional
Hard Disk Interface	1x 2.5 SATA (Share with Key M)	-	-	-	-
Flash Storage	1 x M.2 Key M 2280 (PCIe3.0 x4 or SATA3.0)	1 x M.2 Key M 2280 (PCIe3.0 x4, SATA3.0)	1 x M.2 Key M 2280 (PCIe3.0 x4, SATA3.0)	1 x M.2 Key M 2280 (PCIe3.0 x4, SATA3.0)	1 x M.2 2280 Key M (PCIe3.0 x4)
Display Output	1 x DP++ 1 x HDMI2.0a 1 x eDP (Internal)	2 x HDMI 2.0 1 x LVDS/eDP (Internal)	2 x HDMI 2.0 1 x LVDS/eDP (Internal)	2 x HDMI 2.0 1 x LVDS/eDP (Internal)	1 x HDMI 2.1 1 x DP 1.4 2 x DP 1.4 thru USB-C
Display Resolution Max.	4096 x 2304 60Hz	4096 x 2160 60Hz	4096 x 2160 60Hz	4096 x 2160 60Hz	7680 x 4320 60Hz
Video Capability (Hardware Decode)	AV1, VP9 8/10/12bit, H.265/HEVC 8/10/12 bit, H.264/AVC, MPEG2	8K60 12b 4:2:0 HEVC/VP9/SCC 8K30 10b 4:2:0 AV1 5K60 10b 4:4:4 HEVC/VP9/SCC 4K60 8b 4:2:0 AVC	8K60 12b 4:2:0 HEVC/VP9/SCC 8K30 10b 4:2:0 AV1 5K60 10b 4:4:4 HEVC/VP9/SCC 4K60 8b 4:2:0 AVC	8K60 12b 4:2:0 HEVC/VP9/SCC 8K30 10b 4:2:0 AV1 5K60 10b 4:4:4 HEVC/VP9/SCC 4K60 8b 4:2:0 AVC	8K60 12b 4:2:0 HEVC/VP9/SCC; 8K30 10b 4:2:0 AV1; 5K60 10b 4:4:4 HEVC/VP9/SCC; 4K60 8b 4:2:0 AVC
Audio Output	1 x Line-out (Internal) 1 x Mic-in (Internal) 1 x Speaker (Internal)	1 x Line-out (Internal) 1 x Mic-in (Internal) 1 x Speaker (Internal)	1 x Line-out (Internal) 1 x Mic-in (Internal) 1 x Speaker (Internal)	1 x Line-out (Internal) 1 x Mic-in (Internal) 1 x Speaker (Internal)	-
COM Port	1 x RS232/422/485 (Internal) 1 x RS232 (Internal)	2 x RS232/422/485 4 x RS232 (Internal)	2 x RS232/422/485 2 x RS232 (Internal)	2 x RS232/422/485 4 x RS232 (Internal)	1 x RS232 (Internal)
USB 2.0	4 (Internal)	3 (Edge) 4 (Internal)	3 (Edge) 4 (Internal)	3 (Edge) 4 (Internal)	1 (Internal)
USB3	4	1	1	1	4
Expansion Slot	1 x 1 x M.2 Key E 2230 (PCIe3.0/USB2.0)	1 x M.2 2230 Key E (PCIe4.0 x1/ USB2.0) 1 x M.2 2280 Key M (PCIe x1/ SATA3.0) 1 x M.2 3052/2242 Key B (PCIe4.0 x1/USB3.0/ USB2.0)	1 x 1 x M.2 2230 Key E (PCIe/USB2.0.0) 1 x M.2 2280 Key M (PCIe4.0 x4/SATA3.0) 1 x M.2 3052/2242 Key B (PCIe4.0 x1/USB3.0/ USB2.0)	1 x M.2 2230 Key E (PCIe4.0 x1/ USB2.0) 1 x M.2 2280 Key M (PCIe x1/ SATA3.0) 1 x M.2 3052/2242 Key B (PCIe4.0 x1/USB3.0/ USB2.0)	1 x M.2 Key E 2230 (PCIe/USB2.0) 1 x M.2 Key M 2280 (PCIe3.0 x4)
SIM socket	-	v	v	v	-
Operating Temp.	-20°C to 60°C	-20°C to 80°C	-20°C to 80°C	-20°C to 80°C	0°C to 60°C
DC Input	12V DC	12V DC	12V DC	12V DC	12V DC
Dimension W x D x H (mm)	146 x 102	146 x 102	146 x 102	146 x 102	146 x 102
OS Support	Win10/11/Linux	Win10/11/Linux	Win10/11/Linux	Win10/11/Linux	Win10/Linux
Certification	CE, FCC class A	CE, FCC class A	CE, FCC class A	CE, FCC class A	CE, FCC class A

Model					
	X300	X302	X304-MTX	V1000	V1100
Type	mini-ITX	mini-ITX	mini-ITX	mini-ITX	EPIC
CPU	8th Gen Intel® Core™ (35W, Socket)	9/8th Gen Intel® Core™ (35W Socket)	14/13/12th Gen Intel® Core™ (35W Socket)	AMD Ryzen V1605B Quad Core (15W, SoC)	Intel® Core i5-1145G7E Intel® Core i3-1115G4E (15W, SoC)
Chipset	Intel® PCH Q370/H310	Intel® PCH Q370/H310	Intel® PCH Q670/H610	-	-
Graphics	Intel® UHD Graphics 630	Intel® UHD Graphics 630	Intel® UHD Graphics 770	AMD Radeon Vega 8	Intel® Iris® Xe
Memory	2 x DDR4 SO-DIMM 32GB Max.	2 x DDR4 SO-DIMM 32GB Max.	2 x DDR5 SO-DIMM 64GB Max.	2 x DDR4 SO-DIMM 32GB Max.	2 x DDR4 SO-DIMM 64GB Max.
Gigabit LAN	2	2	2	2	2
WLAN	Optional	Optional	Optional	Optional	Optional
Hard Disk Interface	1 x 2.5" SATA (Q370)	2 x 2.5" SATA	1 x 2.5" SATA	-	-
Flash Storage	1 x M.2 Key M 2280 (Q370: SATA3.0/PCIe x4) (H310: SATA3.0)	1 x M.2 Key B 2242/3042 (Q370: PCIe3.0 x1/SATA3.0) (H310: SATA3.0)	1 x M.2 Key M 2280 (PCIe4.0 x4/SATA3.0)	1 x M.2 Key M 2242/2280 (SATA3.0/PCIe x1)	1 x M.2 Key M 2280 (SATA3.0/PCIe4.0 x4)
Display Output	Q370: 3 x HDMI2.0 H310: 2 x HDMI2.0 + 1x LVDS (Internal)	1 x VGA 1 x HDMI1.4 1 x LVDS (Internal)	3 x HDMI 2.0 1x LVDS (Optional eDP, Internal)	4 x HDMI2.0	4 x HDMI2.0
Display Resolution Max.	4096 x 2160 60Hz	4096 x2160 30Hz	4096 x2160 30Hz	4096 x2160 30Hz	4096 x 2160 60Hz
Video Capability (Hardware Decode)	MPEG-2 (H.262), MPEG-4 (H.264), JPEG/MJPEG, HEVC (H.265), VC-1, VP8, VP9	MPEG-2 (H.262), MPEG-4 (H.264), JPEG/MJPEG, HEVC (H.265), VC-1, VP8, VP9	8K60 12b 4:2:0 HEVC/VP9/SCC; 8K30 10b 4:2:0 AV1; 5K60 10b 4:4:4 HEVC/VP9/SCC; 4K60 8b 4:2:0 AVC	H.264, H.265 / HEVC (8 bit), H.265 / HEVC (10 bit), VP8, VP9, VC-1, AVC, JPEG	H.264, H.265 / HEVC (8 bit), H.265 / HEVC (10 bit), VP8, VP9, VC-1, AVC, JPEG
Audio Output	1 x Line-out (Internal) 1 x Mic-in (Internal)	1 x Line-out (Internal) 1 x Mic-in (Internal) 1 x Speaker (Internal)	1 x Line-out (Internal) 1 x Mic-in (Internal)	1 x Line-out (Internal) 1 x Mic-in (Internal)	1 x Line-out (Internal) 1 x Mic-in (Internal)
COM Port	1 x RS232/422/485 (Internal) 2 x RS232 (Internal)	3 x RS232/422/485 3 x RS232 (Internal)	1x RS232/422/485 (Internal) 3 x RS232 (Internal)	1 x RS232/422/485 (Internal) 3 x RS232 (Internal)	1 x RS232/422/485 (Internal) 1 x RS232 (Internal)
USB 2.0	6 x for Q370 (Internal) 4 x for H310 (Internal)	6 x for Q370 (Internal) 4 x for H310 (Internal)	4 x for Q370 (Internal) 5 x for H310 (Internal)	2 (Internal)	1 (Edge) 4 (Internal)
USB3	4	4	4 (Q670) 3 (H610)	4	3
Expansion Slot	1 x M.2 Key E 2230 (PCIe2.0 x1/USB2.0) 1 x PCIe x16 slot	1 x PCIe x16 1 x M.2 Key E 2230 (PCIe2.0 x1/USB2.0) 1 x M.2 3042/2242 Key B (Q370: PCIe3.0 x1/ SATA3.0) (H310: SATA3.0)	1 x M.2 Key E 2230 (PCIe4.0 x2/USB2.0) 1 x 1 x M.2 Key B 3052 (PCIe3.0 x1/USB3.0/ USB2.0)	1 x M.2 Key E 2230 (PCIe3.0/USB2.0) 1 x PCIe x 8 slot	1 x mini-PCIe (PCIe3.0/USB2.0) 1 x M.2 Key B 3052 (PCIe3.0/USB3.0)
SIM socket	-	v	v	-	v
Operating Temp.	0°C to 60°C	0°C to 60°C	0°C to 60°C	0°C to 60°C	0°C to 60°C
DC Input	12V DC	12V DC	12V DC	12V DC	12V DC
Dimension W x D x H (mm)	170 x170	170 x170	170 x170	170 x170	165 x123
OS Support	Win10/Linux	Win10/Linux	Win10/11/Linux	Win10/Linux	Win10/11/Linux
Certification	CE, FCC class A	CE, FCC class A	CE, FCC class A	CE, FCC class A	CE, FCC class A

Edge AI Computer

Model			
	AIEdge-X®300	AIEdge-X®300-RTX30	AIEdge-X®500
CPU	9/8th Gen Intel® Core™ (65W, Socket)	9/8th Gen Intel® Core™ (65W, Socket)	9/8th Gen Intel® Core™ (95W, Socket)
Chipset	Intel® PCH Q370	Intel® PCH Q370	Intel® PCH Q370
Graphics	Intel® UHD Graphics 630	Intel® UHD Graphics 630	Intel® UHD Graphics 630
Memory	DDR4 SO-DIMM, up to 32GB	DDR4 SO-DIMM, up to 32GB	DDR4 SO-DIMM, up to 32GB
Gigabit LAN	2	2	2
WLAN	Optional	Optional	-
Hard Disk Interface	1 x 2.5" SATA	1 x 2.5" SATA	4 x 2.5" SATA (Hot-Swap)
Flash Storage	1 x M.2 Key M 2280 (SATA3.0/PCIe3.0 x4)	1 x M.2 Key M 2280 (SATA3.0/PCIe3.0 x4)	1 x M.2 Key M 2280 (SATA3.0/PCIe3.0 x4)
Display Output	3 x HDMI2.0	3 x HDMI2.0	1 x HDMI 2.0
Display Resolution Max.	4096 x 2160 60Hz	4096 x 2160 60Hz	4096 x 2160 60Hz
Video Capability (Hardware Decode)	MPEG-2 (H.262), MPEG-4 (H.264), JPEG/ MJPEG, HEVC (H.265), VC-1, VP8, VP9	MPEG-2 (H.262), MPEG-4 (H.264), JPEG/ MJPEG, HEVC (H.265), VC-1, VP8, VP9	MPEG-2 (H.262), MPEG-4 (H.264), JPEG/ MJPEG, HEVC (H.265), VC-1, VP8, VP9
Audio Output	1 x Line-out	1 x Line-out	1 x Line-out
COM Port	1 x RS232 1 x RS232/422/485 1 x RS232 (Internal)	1 x RS232 1 x RS232/422/485 1 x RS232 (Internal)	1 x RS232/422/485 3 x RS232 (Internal)
USB 2.0	4 (Internal)	4 (Internal)	1 (Edge) 6 (Internal)
USB3	4	4	2
Expansion Slot	1 x M.2 Key E 2230 1 x PCIe3.0 x16, two slot space	1 x M.2 Key E 2230 1 x PCIe3.0 x16, two slot space	1 x PCIe3.0 x16, two slot space 1 x PCIe3.0 x4 slot 1 x PCI slot
Add-on Card Length (mm)	204mm Max.	290mm Max.	327mm Max.
Operating Temp.	0°C to 45°C	0°C to 45°C	0°C to 45°C
Power Type	500W ATX power supply	850W ATX power supply	850W ATX power supply
Dimension W x D x H (mm)	360 x 250 x 85	360 x 335 x 85	290 x 360 x 150
OS Support	Win10/Linux	Win10/Linux	Win10/Linux
Gross Weight(kg)	5.8	6.9	9.5
Certification	CE, FCC class A	CE, FCC class A	CE, FCC class A

Model		
	AIEdge-X80	AIEdge-X310
CPU	NVIDIA® Jetson Orin™ NX , up to 70/100 TOPs	14/13/12th Gen Intel® Core™ (Socket, 65W)
Chipset	1024-core NVIDIA® Ampere GPU with 32 Tensor Cores	Intel® PCH H610E
Graphics		Intel® UHD Graphics 770
Memory	8GB 16GB	DDR5 SO-DIMM, up to 64GB
Gigabit LAN	4	2
WLAN	-	-
Hard Disk Interface	-	2 x 2.5" SATA
Flash Storage	1 x M.2 Key M 2280 (PCIe3.0 x4)	1 x M.2 Key M 2242 (SATA3.0/PCIe3.0 x4)
Display Output	1 x HDMI 1.4	2 x DP1.4
Display Resolution Max.	4096 x 2160 60Hz	4096 x 2160 60Hz
Video Capability (Hardware Decode)	Encode: 1x 4K60 (H.265), 3x 4K30 (H.265), 6x 1080p60 (H.265), 12x 1080p30 (H.265) Decode: 1x 8K30 (H.265), 2x 4K60 (H.265), 4x 4K30(H.265), 9x 1080p60(H.265), 18x 1080p30 (H.265)	WMV9, AVC/H.264, JPEG/ MJPEG, HEVC/H.265, VP9, AV1
Audio Output	-	1 x Line out 1 x Mic in
COM Port	1 x RS232/422/485 3 x RS232 (only TX/RX)	1 x RS232 1 x RS232/422/485
USB 2.0	2	2 (Edge) 2 (Internal)
USB3	2	4
Expansion Slot	1 x mini-PCIe 1 x M.2 Key B 3052	1 x M.2 Key E 2230 1 x PCIe4.0 x16 or 2 x PCIe4.0 x8
Add-on Card Length (mm)	-	338mm Max.
Operating Temp.	-20°C to 60°C	0°C to 45°C
Power Type	150W power supply	850W ATX power supply
Dimension W x D x H (mm)	210 x 154 x 50	380 x 390 x 98.5
OS Support	JetPack 5.1.2	Win10/11/Linux
Gross Weight(kg)	2.42	8
Certification	CE, FCC class A	CE, FCC class A

About NEXCOM

Reliable Partner for the AIoT Digital Transformation Solutions

Committed to Customer Success

Founded in 1992 and headquartered in Taipei, Taiwan, NEXCOM is committed to being a trustworthy partner in building the AIoT digital transformation solutions. To surpass customers' expectations, NEXCOM sets itself apart by leveraging its decades of experience in industrial computing, a highly talented R&D team, and exceptional customer service. With these core strengths, NEXCOM has enabled its customers to win key projects in a diverse range of industries.

With its focus on delivering these core values to better serve customers, NEXCOM integrates its capabilities and operates six global businesses: IoT Automation Solutions (IAS), Intelligent Video Surveillance (IDS), Intelligent Platform @ Smart City (IPS), Mobile Computing Solutions

(MCS), Medical & Healthcare Informatics (MHI), Network and Communication Solutions (NCS). This strategic deployment enables NEXCOM to offer time-to-market, time-to-solution products and services without compromising on cost.

In addition, the service-to-market business model gives NEXCOM core competence in building a strong world-class service network by providing customized service, global logistics, local access, and real-time support. Operating six subsidiaries in China, Japan, Taiwan, and the United States, NEXCOM is able to better accommodate customers' requirements as well as closely work with global partners in different regions.

Partners can also be assured that NEXCOM's Taiwan-based Headquarters and subsidiary offices in China and the USA have obtained ISO 9001:2015 Certification.



IAS	IoT Automation Solutions: Industrial Automation & I4.0 Execution, Intelligent Edge, Gateway & EWR, Industrial Robot Control, EtherCAT Motion Solutions, Wireless & Embedded Solutions for Industrial IoT
IDS	Intelligent Video Surveillance: IP Video Surveillance Cameras, Mobile Cameras, ANPR/LPR Network Cameras, Panoramic Cameras, NVR Server Platform
IPS	Intelligent Platform @ Smart City: Smart City, Smart Retail, Digital Signage, Interactive Kiosks, Hospitality, Gateway, Edge AI, and ODM Customization Services
MCS	Mobile Computing Solutions: Edge AI Telematics Computer, Vehicle Telematics Computer, Railway Computer, Vehicle Mount Computer, Vehicle Mount Display, In-Vehicle Networking, In-Vehicle HDMI Extender over IP, Fitness Console
MHI	Medical and Healthcare Informatics: Total Solutions with a Variety of Medical IT Systems
NCS	Network and Communication Solutions: Cyber Security, HPC, Telecommunications, Storage, SDN/NFV, 5G, uCPE, ICS Security

Corporate Vision

To become the industrial leader in providing AIoT digital transformation solutions, NEXCOM utilizes its industry leading technology, localized customer support and worldwide logistics services. This will be achieved by:

- Great team work
- Cooperation with trusted partners
- Growth through innovation

Corporate Mission

- An AIoT digital transformation supplier in vertical application markets
- A quality partner in engineering, manufacturing and services

Business Strategy

Aiming to better support the activities of all its partners, NEXCOM divides its sales force into six dedicated business units to target rapidly expanding vertical markets. This enables each business unit to focus on strategic channel accounts and repeat order business. Moreover, NEXCOM will provide customers with co-marketing strategies, technical support, ODM services, and project support, which are frequently required everywhere.

NEXCOM has already become a business group focused on innovating comprehensive solutions for Industry 4.0. We help our customers deliver vertical solutions optimized for 5G, AI, AIoT, and Industry 4.0 solutions.

Global Fulfillment Service

Product delivery and customer support are always more effective when delivered locally. NEXCOM localizes support and provides a global customer service network to handle all aspects of global business, from presales, order taking, and system assembly to logistics. For expeditious product delivery, NEXCOM has established four regional service centers: Taiwan (for Asia), USA (for North America and South America), and China. Therefore, NEXCOM customers benefit from quality assured product assembly and four service centers.

NEXCOM has invested heavily to establish operational infrastructures, including advanced equipment and facilities, not only at its global headquarters but also at subsidiary offices. Today, each of our service centers, with ISO 9001:2008 certification, has a purpose built assembly line, RMA/ DOA center and warehouse storage capability.

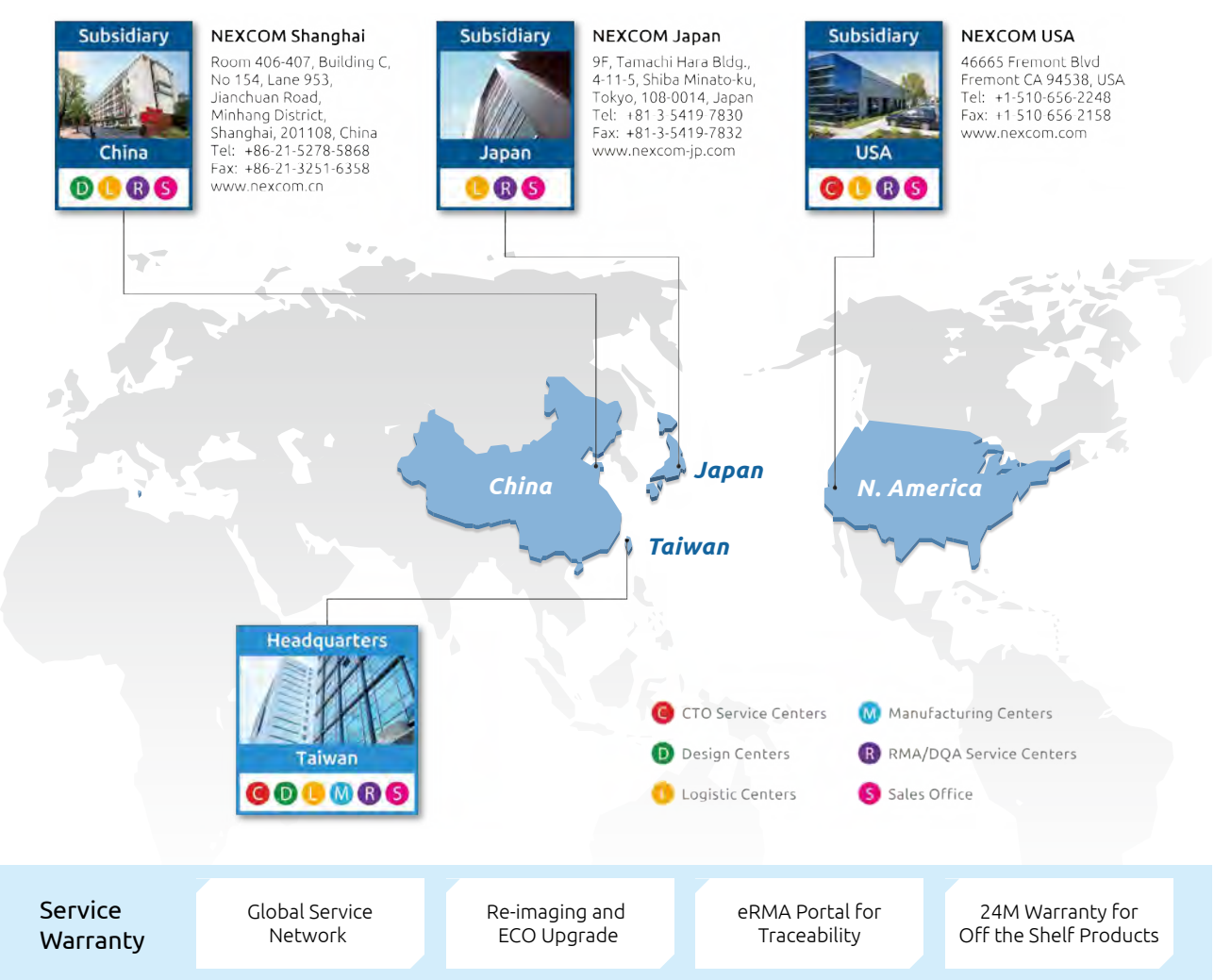
Quality Assurance

Under a strict Quality Assurance System, product design and reliability are controlled to support all critical solutions, and ensure Total Quality Assurance (TQA) implementation for all NEXCOM

products and services. Additionally, NEXCOM's technical support team is aligned with ISO 27001 requirements, as they aim to provide timely feedback within 24 hours to resolve technical issues efficiently. This ensures that any potential information security incidents are addressed promptly, minimizing the impact and downtime for customers.

Green Policy

As a global citizen, NEXCOM places great importance on environmental issues. We are committed to ensuring that our products and services comply with environmental standards and regulations. NEXCOM actively responds to energy-saving and carbon reduction initiatives, prioritizes environmental protection in our operational activities, and holds certificate such as ISO 14064-1 greenhouse gas inventory and ISO 14001 environmental management system. We implement voluntary greenhouse gas inventory, reduce resource and energy consumption, and mitigate environmental risks. We also measure NEXCOM's sustainability and corporate responsibility as an Earth-friendly enterprise through ESG evaluation. NEXCOM will continue to collaborate with peers and suppliers to strive for purification standards, compatibility of technologies, and operational processes to help reduce the potential hazardous substances in our products and manufacturing processes.



Service details may vary by country. Please contact us for more details.

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Committed to Customer Success

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